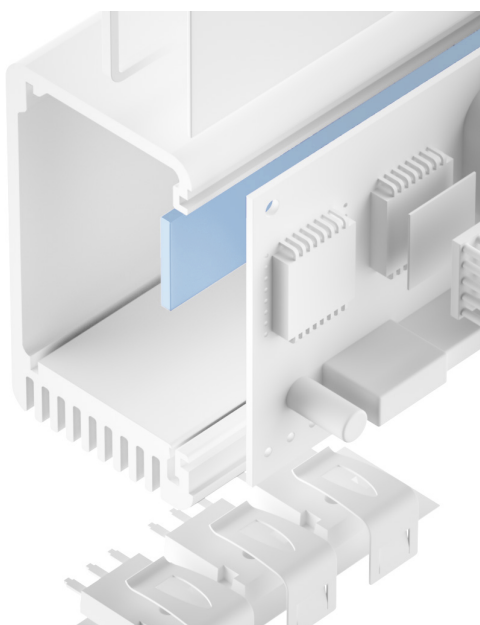


TERMISK LEDENDE MATERIALE

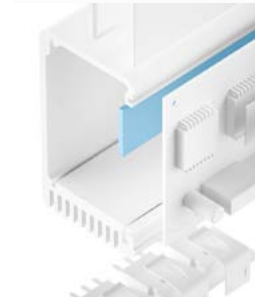


**GAP FILLER
SILICONE**

SILICONE GAP FILLER PAD TGF-M-SI

SOFT, FLEXIBLE

TGF-M-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its high softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable preassembly.



PROPERTIES

- Soft and compliant
- Thermal conductivity: 2.5 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 480 x 460 mm (Thickness 0.5 /1.0 mm)
- Sheet 460 x 460 mm (Thickness 2.0 mm)
- Sheet 450 x 460 mm (Thickness ≥ 2.5 mm)
- Tacky on both sides
- (TGF-MXXXX-SI)
- Tacky on one side
- (TGF-MXXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

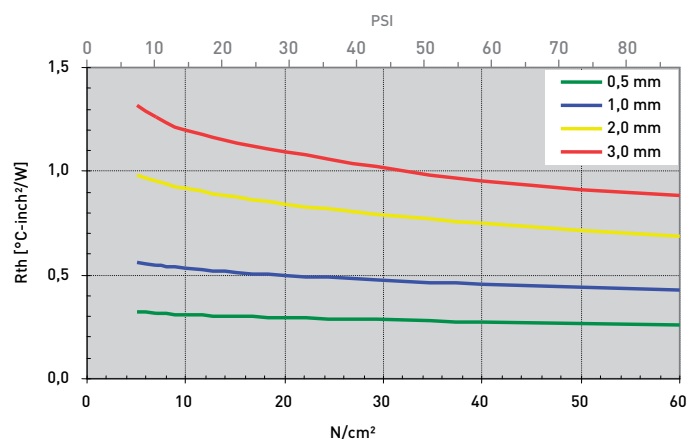
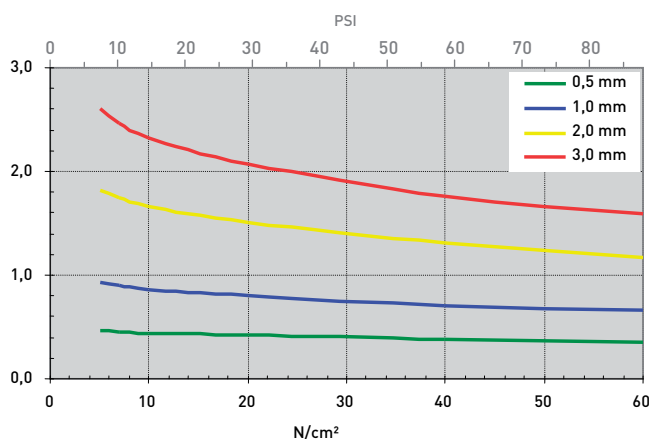
- SMD packages
 - Through-hole vias
 - Capacitors
 - Electronic parts to heat pipes
- For use in Automotive applications / Laptops / Medicine engineering/ Industrial PCs

PROPERTY	UNIT	TGF-M0500-SI	TGF-M1000-SI	TGF-M2000-SI	TGF-M3000-SI
MATERIAL					
Colour		Ceramic filled silicone Light blue	Ceramic filled silicone Light blue	Ceramic filled silicone Light blue	Ceramic filled silicone Light blue
Thickness	mm	0.5 ± 0.05	1.0 ± 0.10	2.0 ± 0.20	3.0 ± 0.30
Hardness	Shore 00	50	50	50	50
UL Flammability	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 60 PSI @ Thickness	$^{\circ}\text{C}\cdot\text{inch}^2/\text{W}$ (mm)	0.27 [0.38]	0.45 [0.71]	0.75 [1.31]	0.96 [1.76]
Resistance ¹ @ 30 PSI @ Thickness	$^{\circ}\text{C}\cdot\text{inch}^2/\text{W}$ (mm)	0.29 [0.42]	0.50 [0.80]	0.84 [1.50]	1.09 [2.07]
Resistance ¹ @ 10 PSI @ Thickness	$^{\circ}\text{C}\cdot\text{inch}^2/\text{W}$ (mm)	0.32 [0.45]	0.55 [0.90]	0.95 [1.75]	1.26 [2.46]
Thermal Conductivity ¹	W/mK	2.5	2.5	2.5	2.5
Operating Temperature Range	$^{\circ}\text{C}$	- 60 to + 180	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICALLY					
Dielectric Strength	kV / mm	10	10	10	10
Volume Resistivity	Ohm - cm	1.0×10^{11}	1.0×10^{11}	1.0×10^{11}	1.0×10^{11}
Dielectric Constant	@ 1 kHz	5.2	5.2	5.2	5.2

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-M-SI

SOFT, FLEXIBLE

TGF-R-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its high softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Soft and compliant
- Thermal conductivity: 3.0 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 480 x 460 mm (Thickness 0.5 /1.0 mm)
- Sheet 460 x 460 mm (Thickness 2.0 mm)
- Sheet 460 x 450 mm (Thickness 3.0/4.0/5.0 mm)
- Tacky on both sides (TGF-MXXX-SI)
- Tacky on one side (TGF-MXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- Capacitors
- Electronic parts to heat pipes

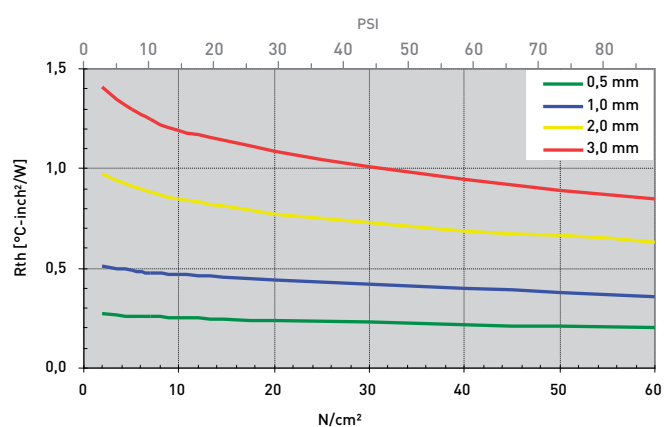
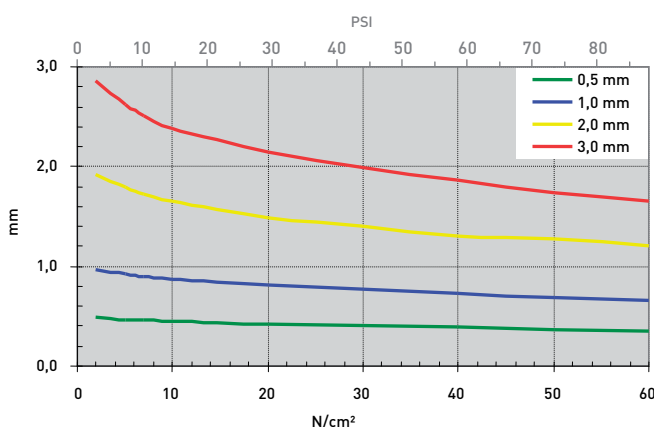
For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs

PROPERTY	UNIT	TGF-R0500-SI	TGF-R1000-SI	TGF-R2000-SI	TGF-R3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Light blue	Light blue	Light blue	Light blue
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20	3.0 ±0.30
Hardness	Shore 00	55	55	55	55
UL Flammability	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.22 [0.39]	0.40 [0.73]	0.68 [1.31]	0.95 [1.86]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.24 [0.42]	0.44 [0.81]	0.77 [1.49]	1.09 [2.15]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.26 [0.46]	0.48 [0.90]	0.88 [1.72]	1.25 [2.50]
Thermal Conductivity ¹	W/mK	3.0	3.0	3.0	3.0
Operating Temperature Range	°C	- 60 to + 180	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICALLY					
Dielectric Strength	kV / mm	10	10	10	10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹¹	1.0 x 10 ¹¹	1.0 x 10 ¹¹	1.0 x 10 ¹¹
Dielectric Constant	@ 1 kHz	5.2	5.2	5.2	5.2

Measurement technique according to: *ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm

mm vs. N/cm² (PSI) / R_{th} vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-XS-SI

SOFT, FLEXIBLE / LOW VOLATILE SILOXANES (LV)

TGF-XS-SI is an electrically insulating thermally conductive high performance LV silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Soft and compliant
- Low volatile siloxane content (LV)
- Thermal conductivity: 6.0 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side self-tacky

AVAILABILITY

- Sheet 400 x 200 mm (≥ 1 mm)
- Sheet 200 x 200 mm (< 1 mm)
- Tacky on both sides (TGF-XSXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

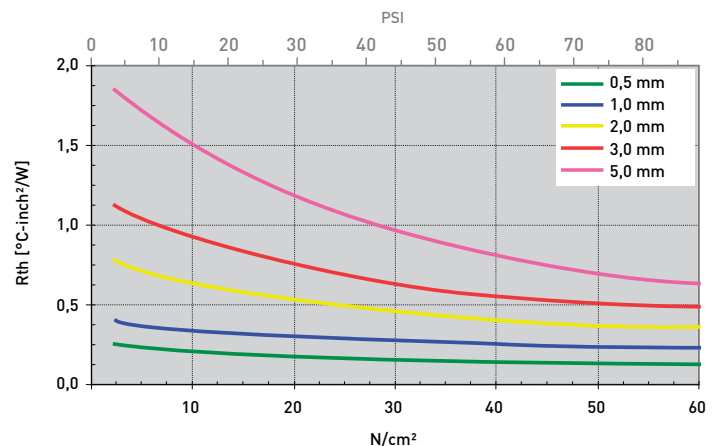
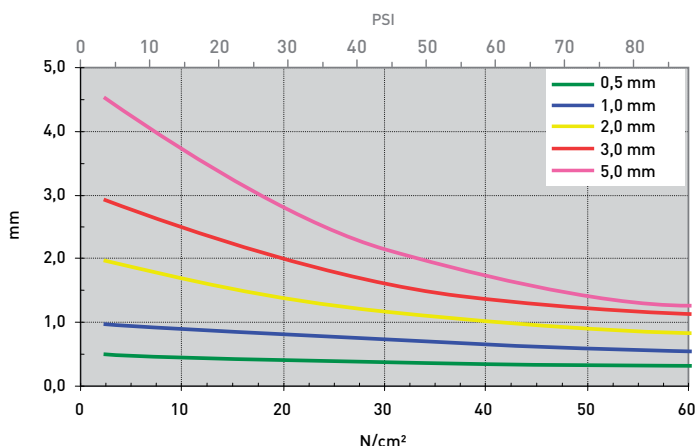
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering/ Embedded boards

PROPERTY	UNIT	TGF-U0500-SI	TGF-U1000-SI	TGF-U2000-SI	TGF-U3000-SI	TGF-U5000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Grey	Grey	Grey	Grey	Grey
Thickness	mm	0.5 ± 0.10	1.0 ± 0.15	2.0 ± 0.20	3.0 ± 0.25	5.0 ± 0.30
Hardness	Shore 00	60	60	60	60	60
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.15 [0.35]	0.27 [0.65]	0.42 [1.03]	0.57 [1.40]	0.84 [1.75]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.17 [0.40]	0.32 [0.81]	0.55 [1.40]	0.78 [1.98]	1.20 [2.75]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.22 [0.45]	0.36 [0.91]	0.68 [1.77]	0.99 [2.63]	1.62 [3.95]
Thermal Conductivity ¹	W/mK	4.5	4.5	4.5	4.5	4.5
Operating Temperature Range	°C	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180
ELECTRICALLY						
Dielectric Strength	kV / mm	15	15	15	15	15

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-VS-SI

SOFT, FLEXIBLE / LOW VOLATILE SILOXANES (LV)

TGF-VS-SI is an electrically insulating thermally conductive high performance LV silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its high softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Soft and compliable
- Low volatile siloxane content (LV)
- Thermal conductivity: 5.0 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side self-tackv

AVAILABILITY

- Sheet 400 x 200 mm
- Tacky on both sides (TGF-VZXXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

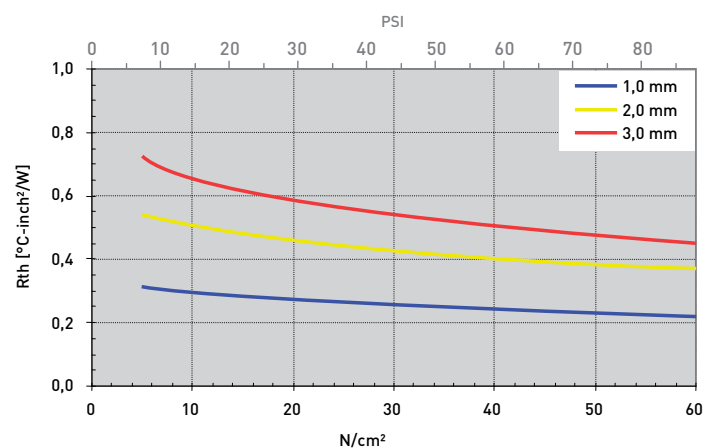
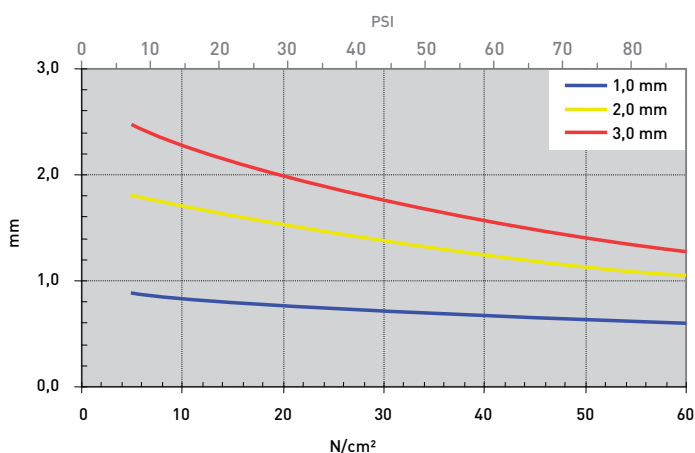
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications
/ Laptops / Medicine engineering
/ Embedded boards

PROPERTY	UNIT	TGF-VS1000-SI	TGF-VS2000-SI	TGF-VS3000-SI
MATERIAL				
		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Turquoise	Turquoise	Turquoise
Density	g/cm ³	3.3	3.3	3.3
Thickness	mm	1.0 ^{+0.20} / _{-0.10}	2.0 ^{+0.20} / _{-0.10}	3.0 ^{+0.30} / _{-0.10}
Hardness	Shore 00	55	55	55
UL Flammability (Equivalent)	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.24 (0.67)	0.40 (1.25)	0.50 (1.55)
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.28 (0.76)	0.46 (1.55)	0.59 (2.00)
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.30 (0.87)	0.52 (1.78)	0.69 (2.42)
Thermal Conductivity ¹	W/mK	5.0	5.0	5.0
Operating Temperature Range	°C	- 40 to + 130	- 40 to + 130	- 40 to + 130
ELECTRICAL				
Dielectric Strength	kV / mm	≥8	≥8	≥8
Volume Resistivity	Ohm - cm	≥1.0 x 10 ¹⁰	≥1.0 x 10 ¹⁰	≥1.0 x 10 ¹⁰

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 3.0 mm

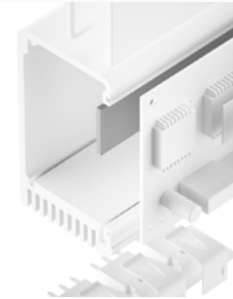
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-U-SI

SOFT, FLEXIBLE

TGF-U-SI is an electrically insulating thermally conductive high performance silicone gap filler. It is ideal for use in applications where a very good thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Soft and compliant
- Thermal conductivity: 4.5 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness

AVAILABILITY

- Sheet 300 x 400 mm
- Tacky on both sides (TGF-UXXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

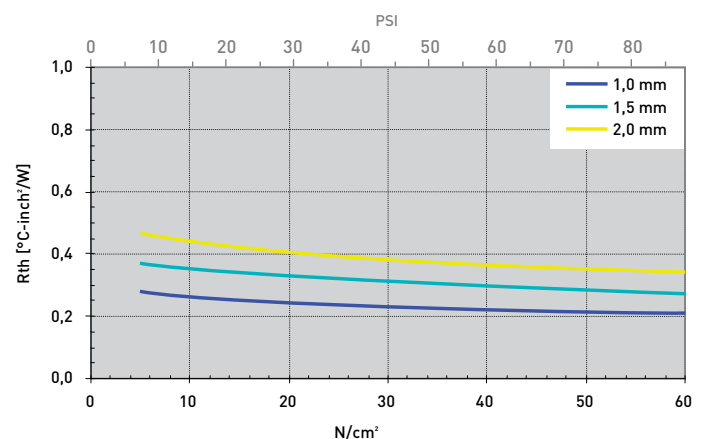
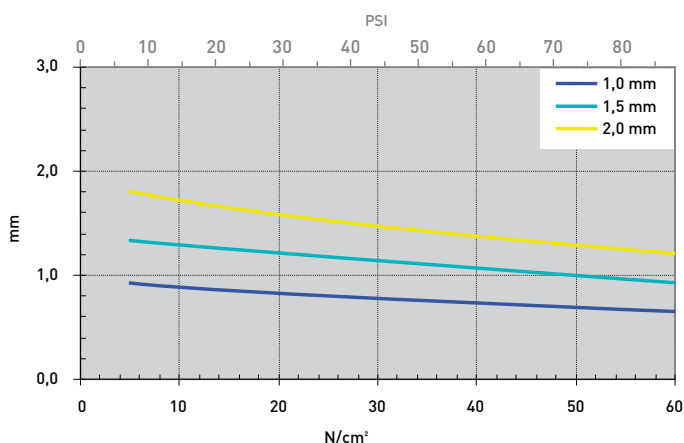
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering/ Embedded boards

PROPERTY	UNIT	TGF-XS1000-SI	TGF-XS1500-SI	TGF-XS2000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Grey	Grey	Grey
Density	g/cm ³	3.3	3.3	3.3
Thickness	mm	1.0 ±0.10	1.5 ±0.15	2.0 ±0.20
Hardness	Shore 00	60	60	60
UL Flammability (Equivalent)	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.22 (0.74)	0.30 (1.07)	0.36 (1.40)
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.24 (0.83)	0.33 (1.22)	0.41 (1.60)
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.27 (0.91)	0.36 (1.32)	0.45 (1.80)
Thermal Conductivity ¹	W/mK	6.0	6.0	6.0
Operating Temperature Range	°C	- 40 to + 130	- 40 to + 130	- 40 to + 130
ELECTRICAL				
Dielectric Strength	kV / mm	≥8	≥8	≥8
Volume Resistivity	Ohm - cm	≥1.0 x 10 ¹⁰	≥1.0 x 10 ¹⁰	≥1.0 x 10 ¹⁰

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.75 mm / 1.0 mm / 1.5 mm / 2.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-Z-SI

SOFT, FLEXIBLE

TGF-Z-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its softness and plasticity the material perfectly mates to irregular surfaces thus optimizing the thermal contact at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly



PROPERTIES

- Soft and compliant
- Thermal conductivity: 11 W/mK
- Operates at low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or Two-side self-tacky

AVAILABILITY

- Sheet 200 x 300 mm
- Tacky on both sides (TGF-ZXXX-SI)
- Tacky on one side by talcum coating (TGF-ZXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Capacitors

For use in Automotive applications
/ Laptops / Medicine engineering
/ Embedded boards

PROPERTY	UNIT	TGF-Z1000-SI	TGF-Z1500-SI	TGF-Z2000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Light grey	Light grey	Light grey
Density	g/cm ³	3.3	3.3	3.3
Hardness	mm	1.0 ±0.2	1.5 ±0.2	2.0 ±0.3
Thickness	Shore 00	64	64	64
UL Flammability (Equivalent)	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹	°C-inch ² /W	0.17 @ 0.90 mm	0.24 @ 1.40 mm	0.30 @ 1.80 mm
Resistance ¹	°C-inch ² /W	0.15 @ 0.70 mm	0.23 @ 1.20 mm	0.27 @ 1.60 mm
Thermal Conductivity	W/mK	11.0	11.0	11.0
Operating Temperature Range	°C	- 50 to + 180	- 50 to + 180	- 50 to + 180
ELECTRICALLY				
Dielectric Strength	kV / mm	>10	>10	>10
Dielectric Constant	Ohm - cm	7.0 x 10 ¹¹	7.0 x 10 ¹¹	7.0 x 10 ¹¹
Volume Resistivity	1 MHz	ca. 7.5	ca. 7.5	ca. 7.5

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 1.0 mm / 1.5 mm / 2.0 mm

SILICONE GAP FILLER PAD TGF-BXS-SI

ULTRA SOFT, FLEXIBLE

TGF-BXS-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a good thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The optional PSA on one side provides for a strong adhesiveness.



PROPERTIES

- Ultra soft and compliant
- Thermal conductivity: 1.2 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side tacky or one-side adhesive

AVAILABILITY

- Sheet 200 x 400 mm
- Tacky on both sides (TGF-BXSXXX-SI)
- PSA adhesive on one side (TGF-BXSXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

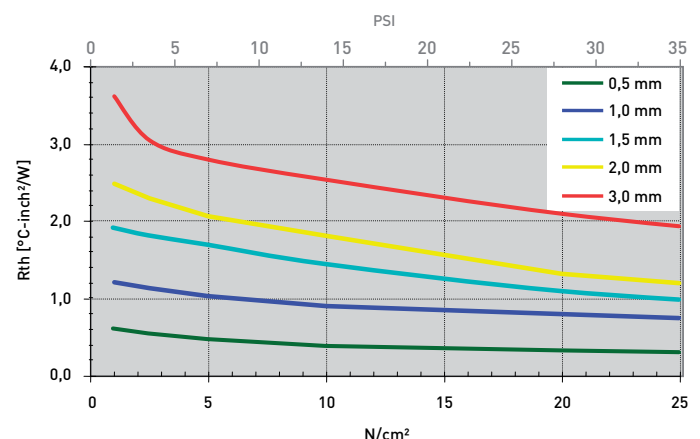
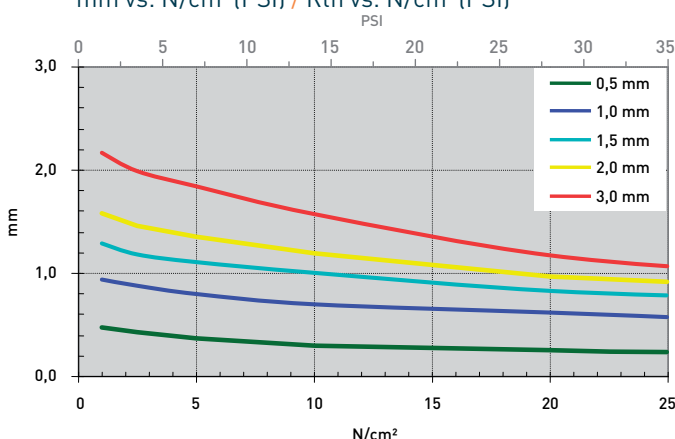
- SMD packages
 - Through-hole vias
 - Capacitors
 - Electronic parts to heat pipes
- For use in Automotive applications / Laptops / Medicine engineering/ Industrial PCs

PROPERTY	UNIT	TGF-BXS0500-SI	TGF-BXS1000-SI	TGF-BXS1500-SI	TGF-BXS2000-SI	TGF-BXS3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Pink	Pink	Pink	Pink	Pink
Thickness	mm	0.5 ±0.10	1.0 ±0.10	1.5 ±0.15	2.0 ±0.20	3.0 ±0.30
Hardness	Shore 00	30	30	30	30	30
Density	g/cm³	2.3	2.3	2.3	2.3	2.3
UL Flammability	UL 94	VO	VO	VO	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance¹ @ 35 PSI @ Thickness	°C-inch²/W (mm)	0.31 (0.24)	0.75 (0.58)	1.00 (0.80)	1.20 (0.92)	1.95 (1.09)
Resistance¹ @ 15 PSI @ Thickness	°C-inch²/W (mm)	0.39 (0.30)	0.90 (0.70)	1.45 (1.01)	1.81 (1.19)	2.54 (1.57)
Resistance¹ @ 7 PSI @ Thickness	°C-inch²/W (mm)	0.48 (0.37)	1.03 (0.80)	1.70 (1.11)	2.07 (1.35)	2.80 (1.84)
Thermal Conductivity¹	W/mK	1.2	1.2	1.2	1.2	1.2
Operating Temperature Range	°C	- 40 to + 150	- 40 to + 150	- 40 to + 150	- 40 to + 150	-40 to + 150
ELECTRIC						
Dielectric Strength	kV / mm	> 6.5	> 6.5	> 6.5	> 6.5	> 6.5
Volume Resistivity	Ohm - cm	3.5 x 10¹²	3.5 x 10¹²	3.5 x 10¹²	3.5 x 10¹²	3.5 x 10¹²
Dielectric Constant	@ 1 MHz	3.87	3.87	3.87	3.87	3.87

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 3.5 mm / 4.0 mm / 4.5 mm / 5.0 mm / .. 12.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-HUS-SI

EXTREMELY SOFT, FLEXIBLE

TGF-HUS-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a good thermal conductivity. Through its extreme softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable preassembly.



PROPERTIES

- Extremely soft and compliant
- Thermal conductivity: 1.8 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side self-tacky

AVAILABILITY

- Sheet 300 x 400 mm
- Tacky on both sides (TGF-HUSXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- Capacitors
- Electronic parts to heat pipes

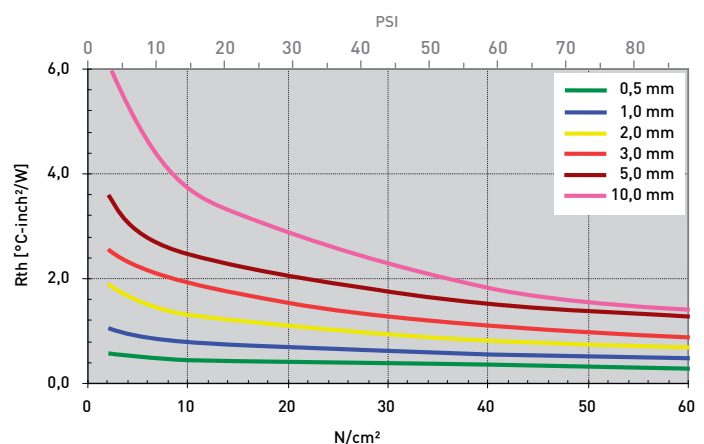
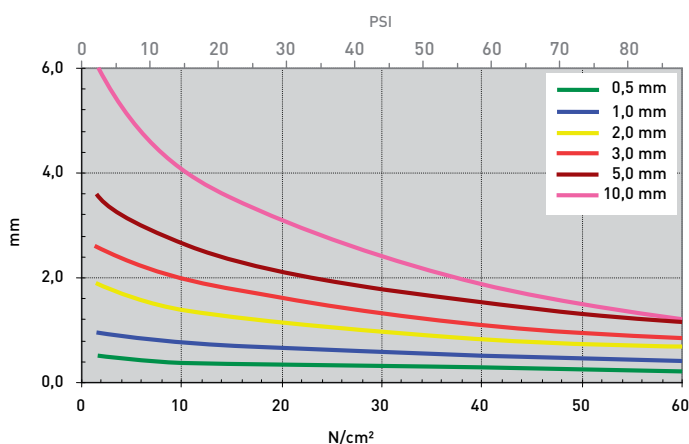
For use in Automotive applications
/ Laptops / Medicine engineering
/ Industrial PCs

PROPERTY	UNIT	TGF-HUS0500-SI	TGF-HUS1000-SI	TGF-HUS2000-SI	TGF-HUS3000-SI	TGF-HUS5000-SI
MATERIAL						
		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Dark grey	Dark grey	Dark grey	Dark grey	Dark grey
Thickness	mm	0.5 ±0.10	1.0 ±0.15	2.0 ±0.20	3.0 ±0.25	5.0 ±0.30
Hardness	Shore 00	30	30	30	30	30
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance ¹ @ 60 PSI @ thickness	°C-inch ² /W (mm)	0.34 [0.31]	0.56 [0.54]	0.82 [0.85]	1.10 [1.09]	1.52 [1.54]
Resistance ¹ @ 30 PSI @ thickness	°C-inch ² /W (mm)	0.40 [0.36]	0.69 [0.68]	1.12 [1.16]	1.53 [1.63]	2.06 [2.13]
Resistance ¹ @ 10 PSI @ thickness	°C-inch ² /W (mm)	0.50 [0.46]	0.85 [0.85]	1.48 [1.57]	2.10 [2.18]	2.71 [2.92]
Thermal Conductivity ¹	W/mK	1.8	1.8	1.8	1.8	1.8
Operating Temperature Range	°C	- 40 to + 150	- 40 to + 150	- 40 to + 150	- 40 to + 150	- 40 to + 150
ELECTRICALLY						
Dielectric Strength	kV / mm	> 10	> 10	> 10	> 10	> 10
Volume Resistivity	Ohm - cm	8.056 x 10 ¹²	8.056 x 10 ¹²	8.056 x 10 ¹²	8.056 x 10 ¹²	8.056 x 10 ¹²
Dielectric Constant	5.6	5.6	5.6	5.6	5.6	5.6

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm / 10.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-JUS-SI

EXTREMELY SOFT, FLEXIBLE

TGF-JUS-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a good thermal conductivity. Through its extreme softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable preassembly.



PROPERTIES

- Extremely soft and compliant
- Thermal conductivity: 2.0 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 480 x 460 mm (Thickness 1.0 mm)
- Sheet 460 x 460 mm (Thickness 2.0 mm)
- Sheet 450 x 460 mm (Thickness ≥ 2.5 mm)
- Tacky on both sides (TGF-JUSXXX-SI)
- PSA adhesive on one side (TGF-JUSXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

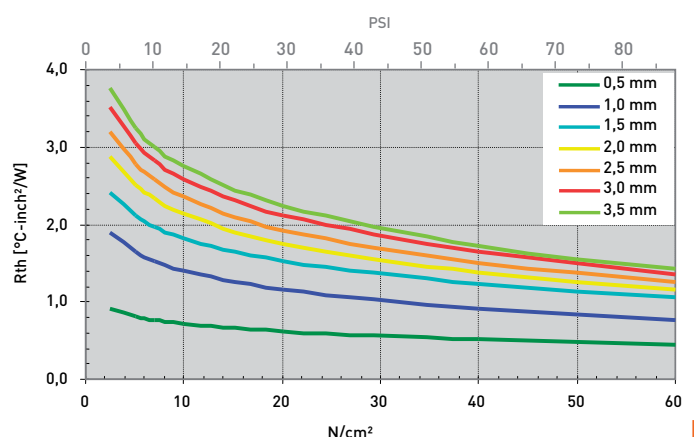
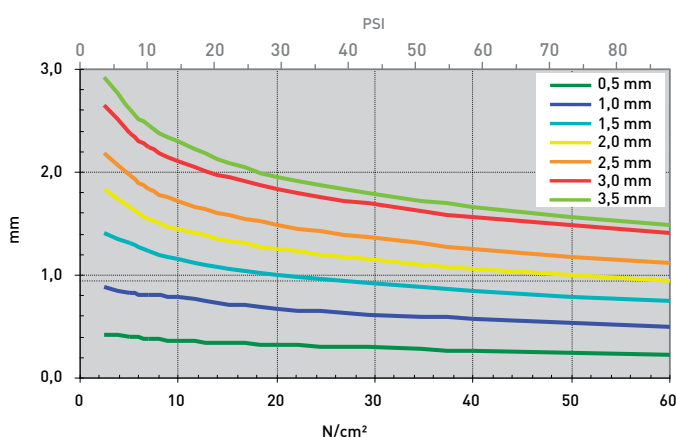
- SMD packages
 - Through-hole vias
 - Capacitors
 - Electronic parts to heat pipes
- For use in Automotive applications / Laptops / Medicine engineering/ Industrial PCs

PROPERTY	UNIT	TGF-JUS0500-SI	TGF-JUS1000-SI	TGF-JUS2000-SI	TGF-JUS3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Grey	Grey	Grey	Grey
Thickness	mm	0.5 ± 0.05	1.0 ± 0.10	2.0 ± 0.20	3.0 ± 0.30
Hardness	Shore 00	20	20	20	20
UL Flammability	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 60 PSI @ thickness	°C-inch ² /W (mm)	0.60 (0.35)	1.00 (0.65)	1.40 (1.10)	1.70 (1.60)
Resistance ¹ @ 30 PSI @ thickness	°C-inch ² /W (mm)	0.70 (0.40)	1.20 (0.75)	1.80 (1.30)	2.10 (1.85)
Resistance ¹ @ 10 PSI @ thickness	°C-inch ² /W (mm)	0.80 (0.45)	1.50 (0.85)	2.30 (1.58)	2.80 (2.25)
Thermal Conductivity ¹	W/mK	2.0	2.0	2.0	2.0
Operating Temperature Range	°C	- 60 to + 180	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICALLY					
Dielectric Strength	kV / mm	10	10	10	10
Volume Resistivity	Ohm - cm	1.0×10^{11}	1.0×10^{11}	1.0×10^{11}	1.0×10^{11}
Dielectric Constant	@ 1 kHz	5	5	5	5

Measurement technique according to: ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 3.5 mm / 4.0 mm / 4.5 mm / 5.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-JXS-SI

ULTRA SOFT, FLEXIBLE / LOW VOLATILE SILOXANES (LV)

TGF-JXS-SI is an electrically insulating thermally conductive LV silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a high thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The material is one-side tacky through lamination with a thermally conductive film.



PROPERTIES

- Ultra soft and compliant
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 2.0 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness

One-side self-tacky

AVAILABILITY

- Sheet 210 x 420 mm (0.5 - 3.0 mm)
- Sheet of 210 x 350 mm (3.5 - 6.0 mm)
- Tacky on one side by film laminate (TGF-JXSXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

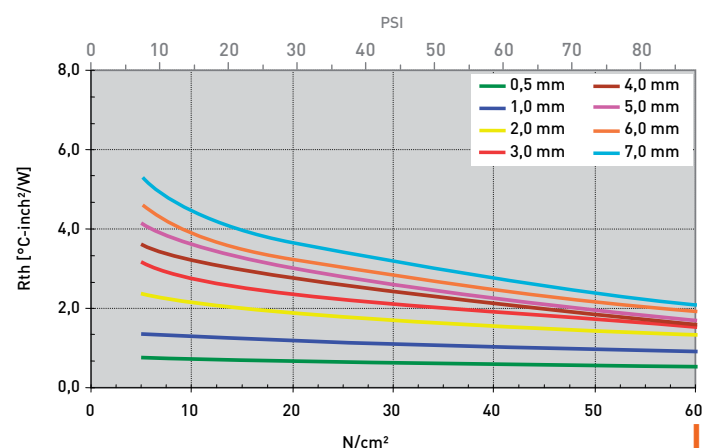
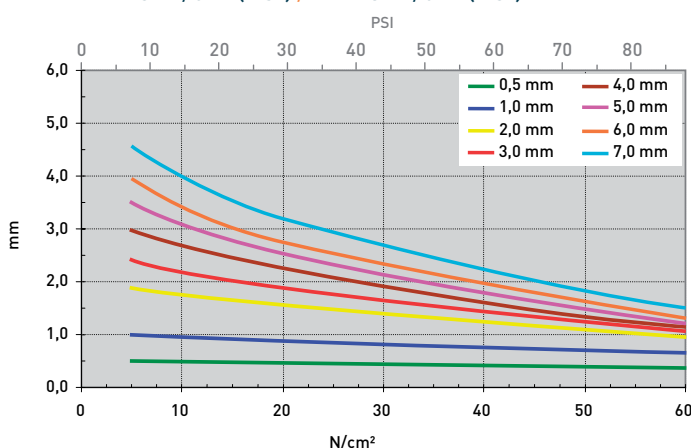
Thermal link of:

- SMD packages
 - Through-hole vias
 - RDRAMs Smemory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications
/ Laptops / Medicine engineering
/ Embedded boards

PROPERTY	UNIT	TGF-JXS0500-SI-A1	TGF-JXS1000-SI-A1	TGF-JXS2000-SI-A1	TGF-JXS3000-SI-A1	TGF-JXS5000-SI-A1
MATERIAL						
Colour		Light blue / Grey	Light blue / Grey	Light blue / Grey	Light blue / Grey	Light blue / Grey
Thickness	mm	0.5 ± ^{0.20} _{0.10}	1.0 ± ^{0.20} _{0.10}	2.0 ± ^{0.20}	3.0 ± ^{0.30}	5.0 ± ^{0.50}
Hardness	Shore 00	20	20	20	20	20
No Paint Wetting Impairment Substances (PWIS) ¹		Passed	Passed	Passed	Passed	Passed
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance ² @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.59 [0.41]	1.03 [0.75]	1.57 [1.25]	1.90 [1.46]	2.26 [1.81]
Resistance ² @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.64 [0.45]	1.16 [0.86]	1.85 [1.55]	2.33 [1.87]	2.98 [2.52]
Resistance ² @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.74 [0.49]	1.32 [0.96]	2.27 [1.82]	2.96 [2.31]	3.89 [3.32]
Thermal Conductivity	W/mK	2.0	2.0	2.0	2.0	2.0
Operating Temperature Range	°C	- 40 to + 200	- 40 to + 200	- 40 to + 200	- 40 to + 200	- 40 to + 200
ELECTRICALLY						
Dielectric Strength	kV / mm	>10	>10	>10	>10	>10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰

Measurement technique according to: ¹IP-VW 3-10.7 57650 Temp. Test, ²ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm / 6.0 mm / 7.0 mm
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-MXS-SI

ULTRASOFT, WITH OR WITHOUT FIBREGLASS REINFORCEMENT

TGF-MXS-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a high thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The optional conductive fibreglass reinforced silicone laminate on one side provides for a high mechanic stability and strength.



PROPERTIES

- Ultra soft and compliable
- Thermal conductivity: 2.4 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 200 x 400 mm
- Tacky on both sides (TGF-MXSXXX-SI)
- Tacky on one side by fibreglass reinforced laminate (TGF-MXSXXX-SI-GF)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

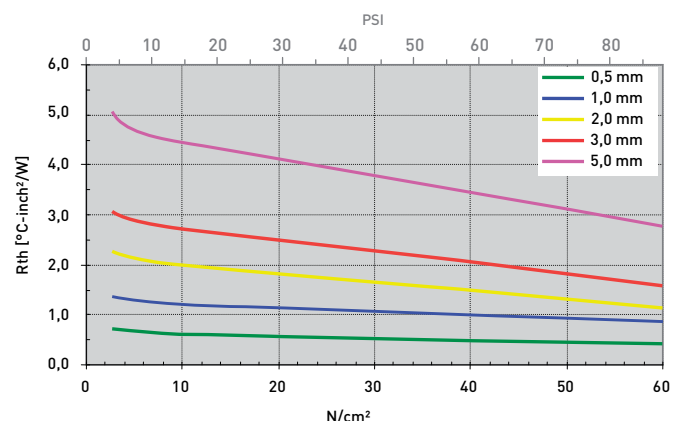
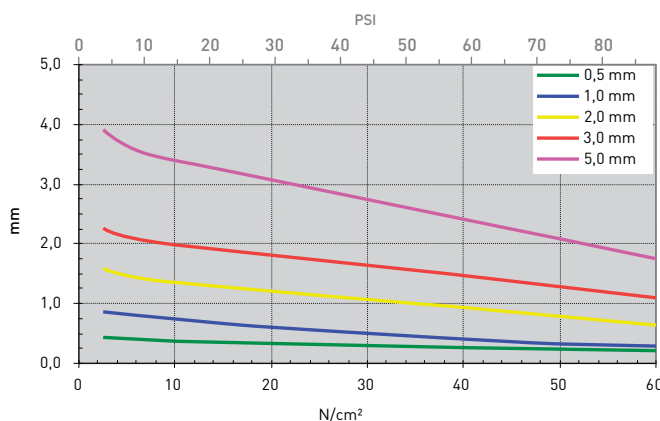
- SMD packages
 - Through-hole vias
 - Capacitors
 - Electronic parts to heat pipes
- For use in Automotive applications / Laptops / Medicine engineering/ Industrial PCs

PROPERTY	UNIT	TGF-MXS0500-SI	TGF-MXS1000-SI	TGF-MXS2000-SI	TGF-MXS3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Grey (/ Red laminate)	Grey (/ Red laminate)	Grey (/ Red laminate)	Grey (/ Red laminate)
Optional Reinforcement (TGF-MXSXXX-SI-GF)		Fibreglass laminate	Fibreglass laminate	Fibreglass laminate	Fibreglass laminate
Thickness	mm	0.5 ±0.10	1.0 ±0.10	2.0 ±0.20	3.0 ±0.30
Hardness	Shore 00	15	15	15	15
UL Flammability	UL 94	V1	V1	V1	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.44 [0.25]	1.00 [0.45]	1.49 [0.86]	2.05 [1.50]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.53 [0.32]	1.15 [0.63]	1.79 [1.15]	2.50 [1.73]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.63 [0.40]	1.26 [0.75]	2.03 [1.40]	2.77 [2.05]
Thermal Conductivity	W/mK	2.4	2.4	2.4	2.4
Operating Temperature Range	°C	- 40 to + 200	- 40 to + 200	- 40 to + 200	- 40 to + 200
ELECTRICAL					
Dielectric Strength	kV / mm	4	4	4	4
Volume Resistivity	Ohm - cm	1.7 x 10 ¹³	1.7 x 10 ¹³	1.7 x 10 ¹³	1.7 x 10 ¹³

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 3.0 mm / 4.0 mm / 5.0 mm / ... / 10.0 mm. Other thicknesses on request

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-LSS-SI

VERY SOFT, FLEXIBLE

TGF-LSS-SI is an electrically insulating thermally conductive high performance silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its extraordinary softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The material can be mechanically reinforced by a fibreglass mesh inlay or a film laminate with fibreglass or by a PI film laminate.



PROPERTIES

- Extraordinary soft and compliant
- Thermal conductivity: 2.5 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side self-tacky

AVAILABILITY

- Sheet 200 x 400 mm
- Two-side self-tacky (TGF-LSSXXX-SI)
- With fibreglass mesh inlay (TGF-LSSXXX-SI-GF)
- With fibreglass reinforced film laminate (TGF-LSSXXX-SI-LGF)
- With PI film laminate (TGF-LSSXXX-SI-LPI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Flip Chips, DSPs, BGAs, PPGAs

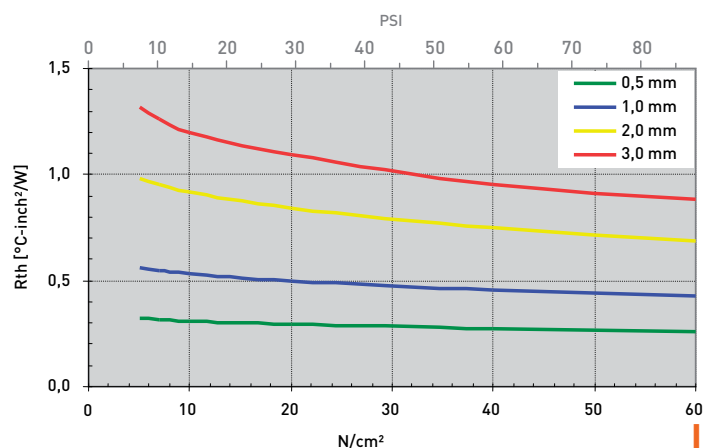
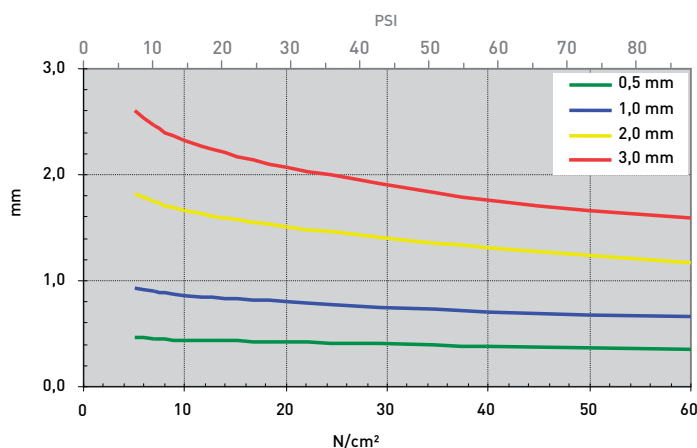
For use in Automotive applications / Laptops / Medical engineering / Embedded boards / Graphic cards / Memory modules/ LED light / LCD and plasma TV

PROPERTY	UNIT	TGF-M0500-SI	TGF-M1000-SI	TGF-M2000-SI	TGF-M3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Light blue	Light blue	Light blue	Light blue
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20	3.0 ±0.30
Hardness	Shore 00	50	50	50	50
UL Flammability	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.27 [0.38]	0.45 [0.71]	0.75[1.31]	0.96 [1.76]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.29 [0.42]	0.50 [0.80]	0.84 [1.50]	1.09 [2.07]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.32 [0.45]	0.55 [0.90]	0.95 [1.75]	1.26 [2.46]
Thermal Conductivity ¹	W/mK	2.5	2.5	2.5	2.5
Operating Temperature Range	°C	- 60 to + 180	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICALLY					
Dielectric Strength	kV / mm	10	10	10	10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹¹	1.0 x 10 ¹¹	1.0 x 10 ¹¹	1.0 x 10 ¹¹
Dielectric Constant	@ 1 kHz	5.2	5.2	5.2	5.2

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm

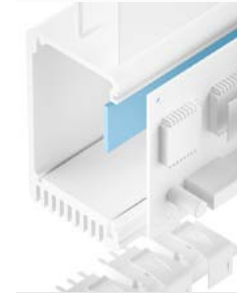
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-MUS-SI

EXTREMELY SOFT, FLEXIBLE

TGF-MUS-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its extreme softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Extremely soft and compliant
- Thermal conductivity: 2.5 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 480 x 460 mm (1.0 mm)
- Sheet 460 x 460 mm (2.0 mm)
- Sheet 450 x 460 mm (3.0 mm)
- Tacky on both sides (TGF-MUSXXX-SI)
- Tacky on one side (TGF-MUSXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

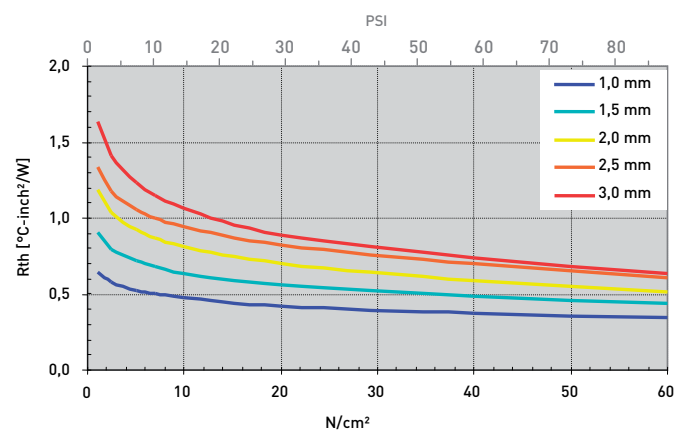
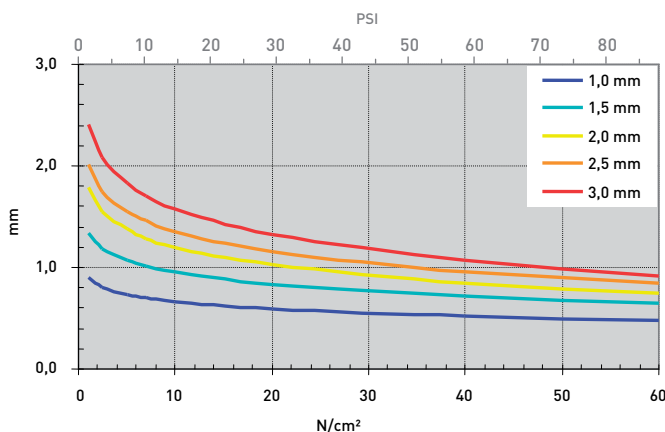
- SMD packages
 - Through-hole vias
 - Capacitors
 - Electronic parts to heat pipes
- For use in Automotive applications / Laptops / Medicine engineering/ Industrial PCs

PROPERTY	UNIT	TGF-MUS1000-SI	TGF-MUS2000-SI	TGF-MUS3000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Light blue	Light blue	Light blue
Thickness	mm	1.0 ±0.10	2.0 ±0.20	3.0 ±0.30
Hardness	Shore 00	20	20	20
UL Flammability	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.37 (0.52)	0.58 (0.85)	0.74 (1.06)
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.42 (0.59)	0.70 (1.02)	0.89 (1.32)
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.49 (0.70)	0.89 (1.29)	1.20 (1.70)
Thermal Conductivity ¹	W/mK	2.5	2.5	2.5
Operating Temperature Range	°C	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICAL				
Dielectric Strength	kV / mm	10	10	10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹¹	1.0 x 10 ¹¹	1.0 x 10 ¹¹
Dielectric Constant	@ 1 kHz	5.2	5.2	5.2

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 1.0 mm / 1.5 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm

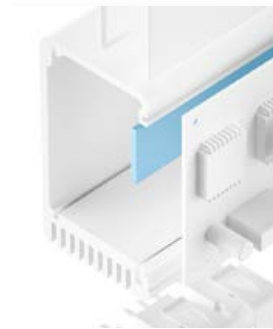
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-RSS-SI

VERY SOFT, FLEXIBLE

TGF-RSS-SI is an electrically insulating thermally conductive high performance silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its extraordinary softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The material can be mechanically reinforced by a fibreglass mesh inlay or a film laminate with fibreglass or by a PI film laminate.



PROPERTIES

- Extraordinary soft and compliant
- Thermal conductivity: 3.0 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- Two-side self-tacky

AVAILABILITY

- Sheet 200 x 400 mm
- Two-side self-tacky (TGF-RSSXXX-SI)
- With fibreglass mesh inlay (TGF-RSSXXX-SI-GF)
- With fibreglass reinforced film laminate (TGF-RSSXXX-SI-LGF)
- With PI film laminate (TGF-RSSXXX-SI-LPI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

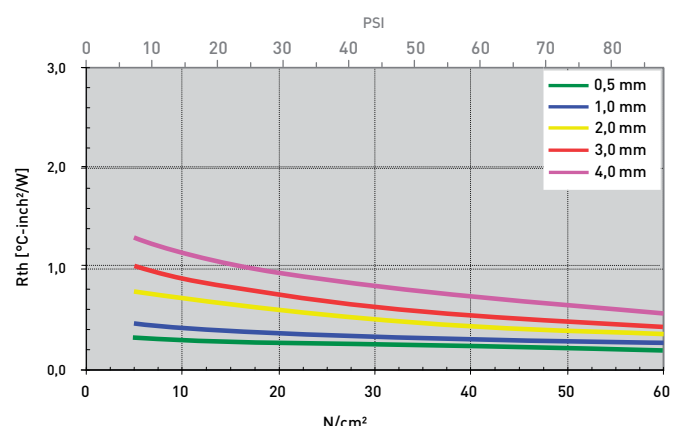
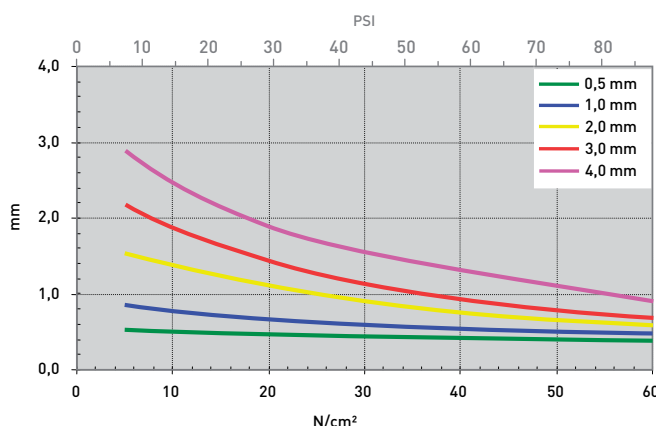
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medical engineering / Embedded boards / Graphic cards / Memory modules / LED light / LCD and plasma TV

PROPERTY	UNIT	TGF-RSS0500-SI	TGF-RSS1000-SI	TGF-RSS2000-SI	TGF-RSS3000-SI	TGF-RSS4000-SI
MATERIAL						
Colour		Ceramic filled silicone Light blue	Ceramic filled silicone Light blue	Ceramic filled silicone Light blue	Ceramic filled silicone Light blue	Ceramic filled silicone Light blue
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20	3.0 ±0.30	4.0 ±0.40
Hardness	Shore 00	43	43	43	43	43
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.25 (0.41)	0.31 (0.52)	0.44 (0.73)	0.54 (0.93)	0.74 (1.33)
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.27 (0.44)	0.37 (0.67)	0.59 (1.10)	0.75 (1.44)	0.95 (1.89)
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.30 (0.48)	0.45 (0.81)	0.75 (1.48)	0.99 (2.08)	1.25 (2.74)
Thermal Conductivity ¹	W/mK	3.0	3.0	3.0	3.0	3.0
Operating Temperature Range	°C	- 50 to + 170	- 50 to + 170	- 50 to + 170	- 50 to + 170	- 50 to + 170
ELECTRICAL						
Dielectric Strength	kV / mm	>7.0	>7.0	>7.0	>7.0	>7.0
Volume Resistivity	Ohm - cm	1.0 x 10 ¹³	1.0 x 10 ¹³	1.0 x 10 ¹³	1.0 x 10 ¹³	1.0 x 10 ¹³
Dielectric Constant	@ 1 MHz	5.6	5.6	5.6	5.6	5.6

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 3.0 mm / 4.0 mm / 5.0 mm / ... / 10.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-TSS-SI

VERY SOFT, FLEXIBLE

TGF-TSS-SI is an electrically insulating thermally conductive high performance silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a very high thermal conductivity. Through its extraordinary softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Extremely soft and compliant
- Thermal conductivity: 3.2 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness

AVAILABILITY

- Sheet 300 x 400 mm
- Tacky on both sides (TGF-TSSXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

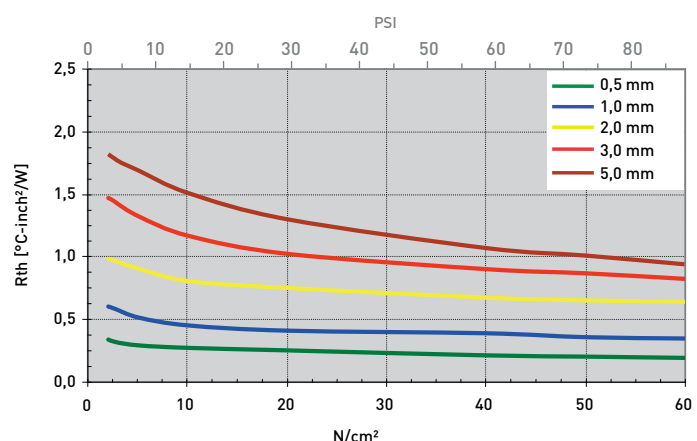
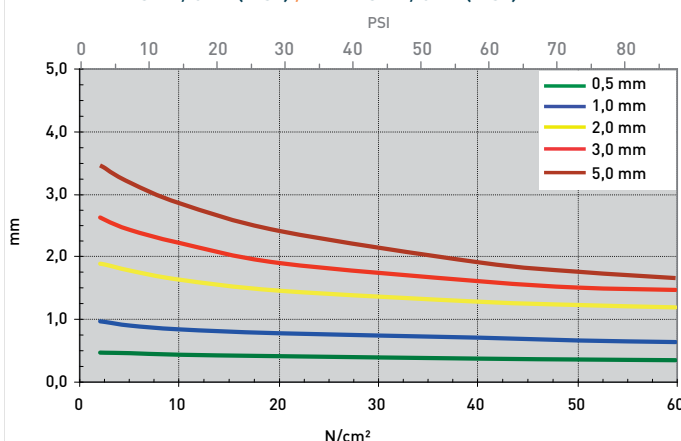
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering / Embedded boards

PROPERTY	UNIT	TGF-TSS0500-SI	TGF-TSS1000-SI	TGF-TSS2000-SI	TGF-TSS3000-SI	TGF-TSS5000-SI
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Light reddish purple	Light reddish purple	Light reddish purple	Light reddish purple	Light reddish purple
Thickness	mm	0.5 ±0.10	1.0 ±0.15	2.0 ±0.20	3.0 ±0.25	5.0 ±0.30
Hardness	Shore 00	37	37	37	37	37
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.22 [0.37]	0.40 [0.70]	0.68 [1.27]	0.91 [1.60]	1.08 [1.90]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.26 [0.41]	0.42 [0.77]	0.76 [1.45]	1.03 [1.89]	1.31 [2.40]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.29 [0.44]	0.49 [0.86]	0.86 [1.70]	1.25 [2.31]	1.61 [3.01]
Thermal Conductivity ¹	W/mK	3.2	3.2	3.2	3.2	3.2
Operating Temperature Range	°C	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180
ELECTRICALLY						
Dielectric Strength	kV / mm	15	15	15	15	15

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 2.5 mm / 3.0 mm / 4.0 mm / 5.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-USS-SI

VERY SOFT, FLEXIBLE / LOW VOLATILE SILOXANES (LV)

TGF-USS-SI is an electrically insulating thermally conductive high performance LV silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic articles the silicone elastomer has a very high thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The material is one-side tacky through lamination with a thermally conductive film.



PROPERTIES

- Ultra soft and compliant
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 3.3 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One-side self-tacky

AVAILABILITY

- Sheet 210 x 420 mm (0.5 - 3.0 mm)
- Tacky on one side by film laminate (TGF-USSXXX-SI-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

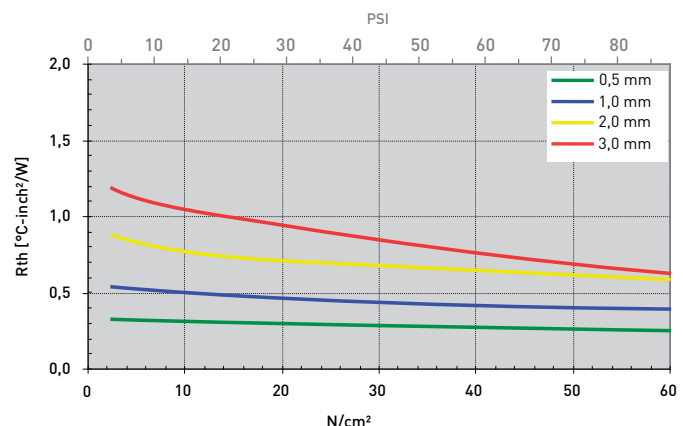
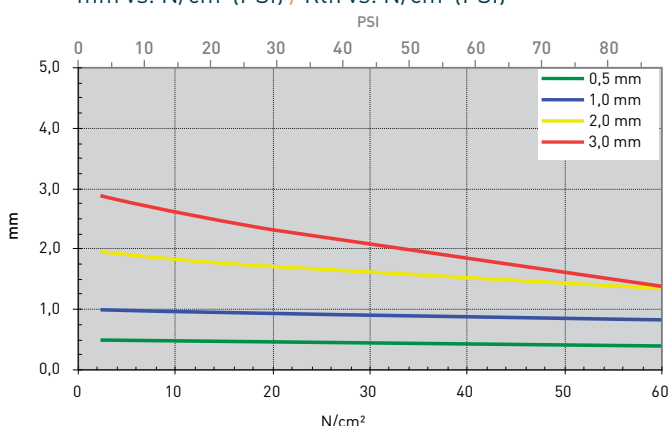
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications
/ Laptops / Medicine engineering
/ Embedded boards

PROPERTY	UNIT	TGF-USS0500-SI-A1	TGF-USS1000-SI-A1	TGF-USS2000-SI-A1	TGF-USS3000-SI-A1
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Dark grey / Grey	Dark grey / Grey	Dark grey / Grey	Dark grey / Grey
Thickness	mm	0.5 ± 0.20 -0.10	1.0 ± 0.20 -0.10	2.0 ± 0.20	3.0 ± 0.30
Hardness	Shore 00	45	45	45	45
No Paint Wetting Impairment Substances (PWIS) ¹		Passed	Passed	Passed	Passed
UL Flammability (Equivalent)	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ² @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.26 [0.47]	0.40 [0.87]	0.63 [1.55]	0.75 [1.84]
Resistance ² @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.29 [0.48]	0.45 [0.93]	0.70 [1.70]	0.94 [2.30]
Resistance ² @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.31 [0.49]	0.51 [0.99]	0.80 [1.85]	1.07 [2.68]
Thermal Conductivity ¹	W/mK	3.3	3.3	3.3	3.3
Operating Temperature Range	°C	- 40 to + 150	- 40 to + 150	- 40 to + 150	- 40 to + 150
ELECTRICAL					
Breakdown Voltage	kV / mm	>10	>10	>10	>10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰	1.0 x 10 ¹⁰

Test Methods: ¹P-VW 3-10.7 57650 Temp. Test, ²ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 3.0 mm

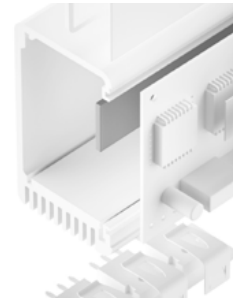
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-WSS-SI

VERY SOFT, FLEXIBLE

TGF-WSS-SI is an electrically insulating thermally conductive high performance silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its high softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at very low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Very soft and compliant
- Thermal conductivity: 5.5 W/mK
- Operates at very low pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One or two-side self-tacky

AVAILABILITY

- Sheet 460 x 100 mm
- Tacky on both sides (TGF-WSSXXX-SI)
- Tacky on one side (TGF-WSSXXX-A1)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Flip Chips, DSPs, BGAs, PPGAs

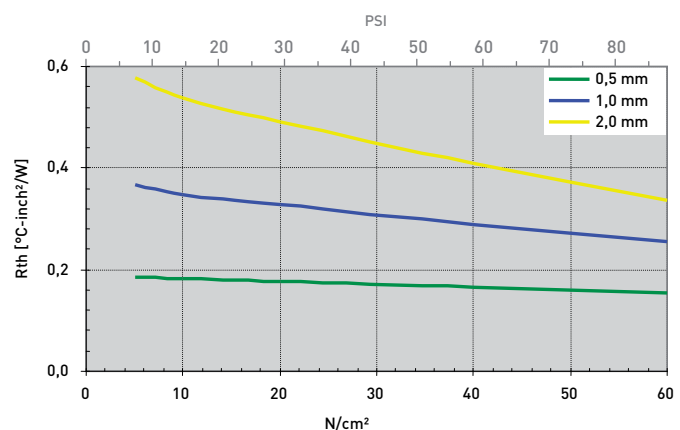
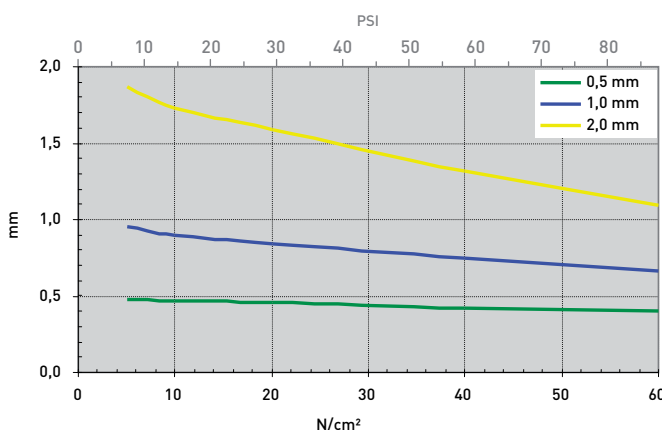
For use in Automotive applications / Laptops / Medicine engineering / Embedded boards

PROPERTY	UNIT	TGF-WSS0500-SI	TGF-WSS1000-SI	TGF-WSS2000-SI
MATERIAL				
Colour		Grey	Grey	Grey
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20
Hardness	Shore 00	55	55	55
UL Flammability	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.16 [0.41]	0.30 [0.75]	0.41 [1.32]
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.18 [0.46]	0.32 [0.85]	0.49 [1.59]
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.19 [0.48]	0.36 [0.93]	0.56 [1.80]
Thermal Conductivity ¹	W/mK	5.5	5.5	5.5
Operating Temperature Range	°C	- 60 to + 180	- 60 to + 180	- 60 to + 180
ELECTRICAL				
Dielectric Strength	kV / mm	10	10	10
Volume Resistivity	Ohm - cm	1.0 x 10 ¹³	1.0 x 10 ¹³	1.0 x 10 ¹³

Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-DXS-SI-GF

ULTRA SOFT, WITH FIBREGLASS REINFORCEMENT

TGF-DXS-SI-GF is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a good thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The conductive fibreglass reinforced silicone laminate on one side provides for a high mechanic stability and strength.



PROPERTIES

- Ultra soft and compliant
- Thermal conductivity: 1.3 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One-side self-tacky

AVAILABILITY

- Sheet 200 x 400 mm (0.5 - 3.0 mm)
- Tacky on one side by fibreglass reinforced laminate (TGF-DXSXXX-SI-GF)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- Capacitors
- Electronic parts to heat pipes

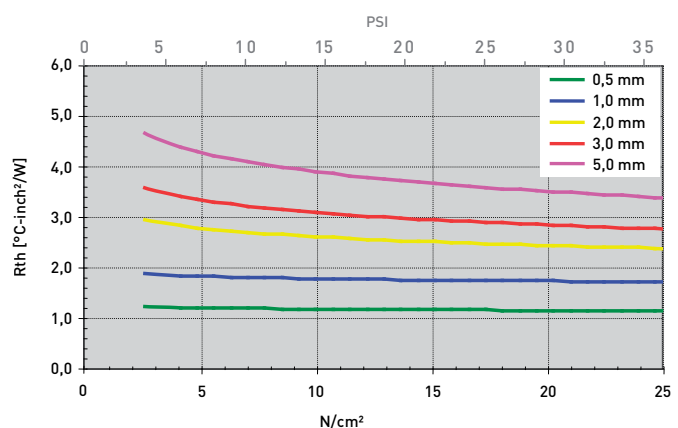
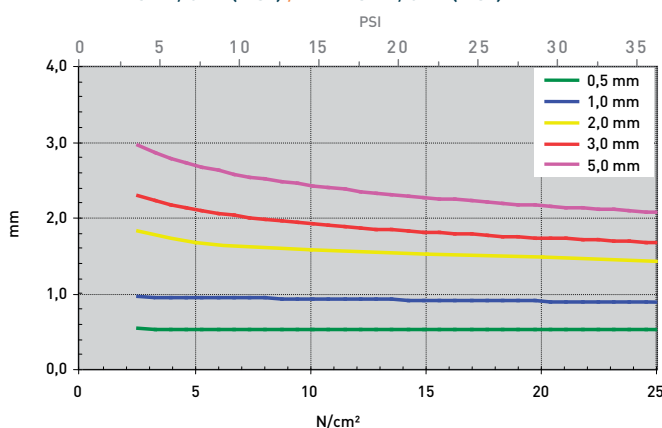
For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs

PROPERTY	UNIT	TGF-DXS1000-SI-GF	TGF-DXS2000-SI-GF	TGF-DXS3000-SI-GF	TGF-DXS5000-SI-GF
MATERIAL					
Colour		White / Pink	White / Pink	White / Pink	White / Pink
Reinforcement		Fibreglass laminate	Fibreglass laminate	Fibreglass laminate	Fibreglass laminate
Thickness	mm	1.0 ± 0.10 -0.01	2.0 ± 0.20 -0.02	3.0 ± 0.30 -0.03	5.0 ± 0.50 -0.05
Hardness	Shore 00	5	5	5	5
UL Flammability	UL 94	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes
THERMAL					
Resistance ¹ @ 35 PSI @ Thickness	°C-inch ² /W (mm)	1.77 (0.94)	2.43 (1.40)	2.80 (1.65)	3.40 (2.10)
Resistance ¹ @ 15 PSI @ Thickness	°C-inch ² /W (mm)	1.85 (0.95)	2.70 (1.60)	3.10 (1.95)	3.95 (2.55)
Resistance ¹ @ 7 PSI @ Thickness	°C-inch ² /W (mm)	1.86 (0.97)	2.80 (1.70)	3.30 (2.20)	4.40 (2.70)
Thermal Conductivity	W/mK	1.3	1.3	1.3	1.3
Operating Temperature Range	°C	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180
ELECTRICAL					
Dielectric Strength	kV / mm	6	6	6	6
Volume Resistivity	Ohm - cm	6.2×10^{15}	6.2×10^{15}	6.2×10^{15}	6.2×10^{15}
Dielectric Constant	@ 1 MHz	5.27	5.27	5.27	5.27

Measurement technique according to: ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 2.0 mm / 3.0 mm / 4.0 mm / 5.0 mm / 6.0 mm / 7.0 mm / 8.0 mm / 9.0 mm / 10.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-EXS-SI-GF

ULTRA SOFT, FLEXIBLE

TGF-EXS-SI-GF is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has a high thermal conductivity. Through its ultra softness and flexibility the material perfectly mates to irregular surfaces thus filling gaps at minimum pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly. The conductive fiberglass reinforced silicone laminate on one side allows for a high mechanic stability and strength.



PROPERTIES

- Ultra soft and compliant
- Thermal conductivity: 1.4 W/mK
- Operates at minimum pressure
- Extraordinary chemical resistance and longterm stability
- Shock absorbing
- Easy mounting through self tackiness
- One-side self-tacky

AVAILABILITY

- Sheet 300 x 400 mm
- Tacky on one side by fiberglass reinforced laminate (TGF-EXSXXX-SI-GF)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

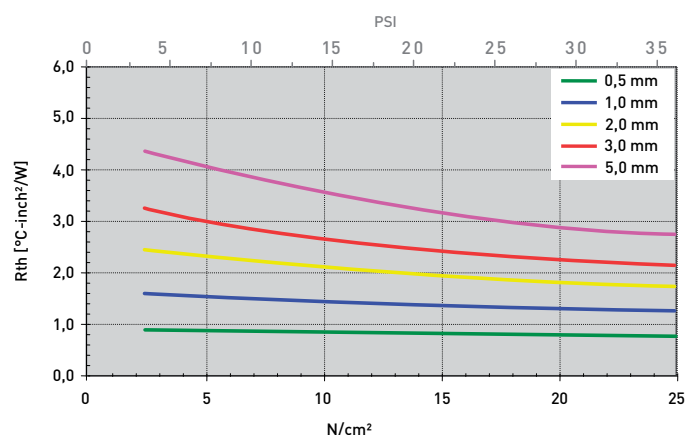
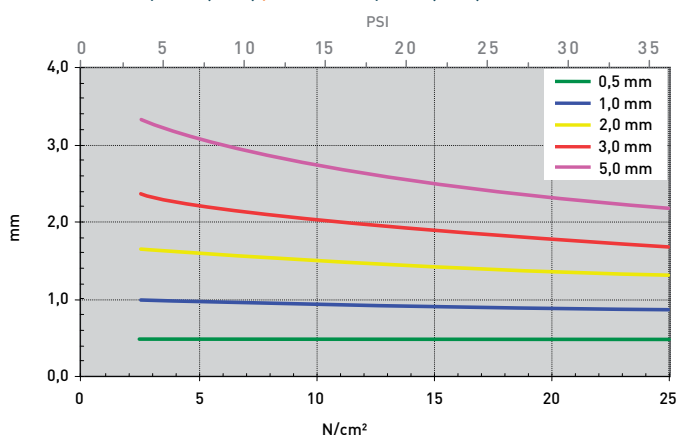
- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering / Embedded boards

PROPERTY	UNIT	TGF-EXS0500-SI-GF	TGF-EXS1000-SI-GF	TGF-EXS2000-SI-GF	TGF-EXS3000-SI-GF	TGF-EXS5000-SI-GF
MATERIAL		Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone	Ceramic filled silicone
Colour		Reddish brown / Grey	Reddish brown / Grey	Reddish brown / Grey	Reddish brown / Grey	Reddish brown / Grey
Reinforcement		Fibreglass laminate	Fibreglass laminate	Fibreglass laminate	Fibreglass laminate	Fibreglass laminate
Thickness	mm	0.5 ±0.10	1.0 ±0.15	2.0 ±0.25	3.0 ±0.25	5.0 ±0.30
Hardness	Shore 00	10	10	10	10	10
UL Flammability	UL 94	V0	V0	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes	Yes	Yes
THERMAL						
Resistance¹ @ 35 PSI @ Thickness	°C-inch²/W (mm)	0.76 [0.46]	1.26 [0.86]	1.73 [1.30]	2.14 [1.68]	2.73 [2.17]
Resistance¹ @ 15 PSI @ Thickness	°C-inch²/W (mm)	0.85 [0.47]	1.44 [0.92]	2.07 [1.50]	2.63 [2.03]	3.58 [2.72]
Resistance¹ @ 7 PSI @ Thickness	°C-inch²/W (mm)	0.89 [0.48]	1.54 [0.95]	2.31 [1.58]	3.00 [2.20]	4.08 [3.06]
Thermal Conductivity¹	W/mK	1.4	1.4	1.4	1.4	1.4
Operating Temperature Range	°C	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180	- 40 to + 180
ELECTRICALLY						
Dielectric Strength	kV / mm	20	20	20	20	20

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 3.0 mm / 4.0 mm / 5.0 mm

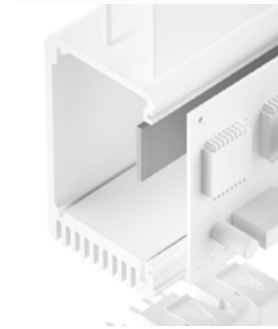
mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-YP-SI

PLASTIC

TGF-YP-SI is an electrically insulating thermally conductive very high performance silicone gap filler. It is ideal for use in applications where a very good thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an outstandingly high thermal conductivity. Through its softness and plasticity the material perfectly mates to irregular surfaces thus filling gaps at low pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.



PROPERTIES

- Plastic
- Soft and compliant
- Thermal conductivity: 7.0 W/mK
- Extraordinary chemical resistance and longterm stability
- Two-side self-tacky

AVAILABILITY

- Sheet 460 x 100 mm
- Tacky on both sides (TGF-YPXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- Capacitors
- Electronic parts to heat pipes

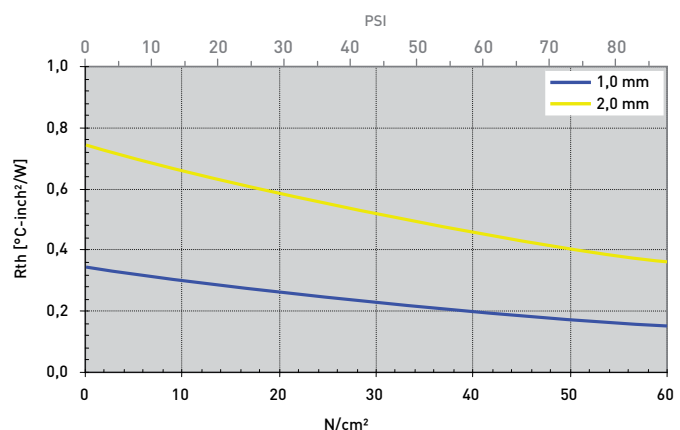
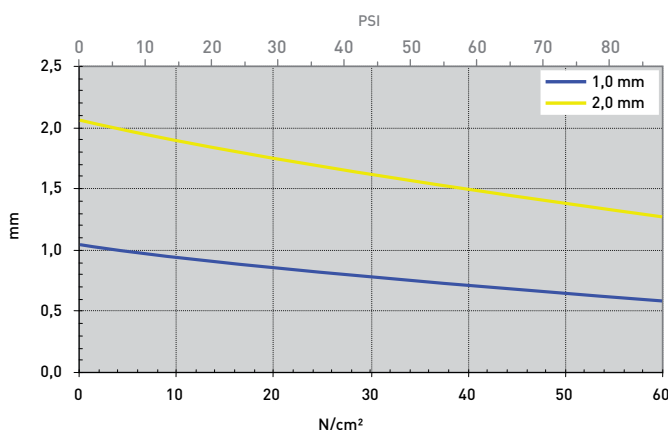
For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs

PROPERTY	UNIT	TGF-YP1000-SI	TGF-YP2000-SI
MATERIAL			
Colour		Ceramic filled silicone Grey	Ceramic filled silicone Grey
Thickness	mm	1.0 ± 0.10	2.0 ± 0.20
Hardness	Shore 00	55	55
UL Flammability (Equivalent)	UL 94	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes
THERMAL			
Resistance ¹ @ 60 PSI @ Thickness	°C-inch ² /W (mm)	0.20 (0.75)	0.45 (1.50)
Resistance ¹ @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.27 (0.90)	0.59 (1.75)
Resistance ¹ @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.32 (0.95)	0.67 (1.90)
Thermal Conductivity	W/mK	7.0	7.0
Operating Temperature Range	°C	- 40 to + 150	- 40 to + 150
ELECTRICALLY			
Dielectric Strength	kV / mm	>10	>10
Volume Resistivity	Ohm - cm	> 1.0 x 10 ¹²	> 1.0 x 10 ¹²
Dielectric Constant	@ 1 MHz	7	7

Measurement technique according to: *ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 1.0 mm / 2.0 mm / 3.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TGF-ZP-SI

PLASTIC



TGF-ZP-SI is an electrically insulating thermally conductive silicone gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. Due to the specific formulation and filling with ceramic particles the silicone elastomer has an extremely high thermal conductivity. Through its extreme softness and plasticity the material perfectly mates to irregular surfaces thus filling gaps at almost zero pressure. By its use the total thermal resistance is minimised. The natural tackiness of the material allows for an easy and reliable pre-assembly.

PROPERTIES

- Plastic
- Extremely soft and compliant
- Thermal conductivity: 11 W/mK
- Operates at almost zero pressure
- For minimal gaps
- Extraordinary chemical resistance and longterm stability
- Easy mounting through self tackiness

AVAILABILITY

- Sheet 300 x 200 mm
- Tacky on both sides (TGF-ZPXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Capacitors

For use in Automotive applications / Laptops / Medicine engineering / Embedded boards

PROPERTY	UNIT	TGF-ZP1500-SI	TGF-ZP2000-SI
MATERIAL			
		Ceramic filled silicone	Ceramic filled silicone
Colour		Light grey	Light grey
Reinforcement		None	None
Thickness	mm	1.5 ^{+0.50} / _{-0.00}	2.0 ^{+0.70} / _{-0.00}
Density	g/cm ³	3.3	3.3
UL Flammability	UL 94	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes
THERMAL			
Resistance ¹ @ 1.5 mm	°C-inch ² /W	---	0.24
Resistance ¹ @ 0.8 mm	°C-inch ² /W	0.14	0.14
Resistance ¹ @ 0.5 mm	°C-inch ² /W	0.10	0.10
Resistance ¹ @ 0.2 mm	°C-inch ² /W	0.06	0.06
Thermal Conductivity	W/mK	11	11
Operating Temperature Range	°C	- 50 to + 180	-50 to + 180
ELECTRICAL			
Dielectric Strength	kV / mm	11	11
Dielectric Constant	@ 1 MHz	7.5	7.5
Volume Resistivity	Ohm - cm	7.0 x 10 ⁷	7.0 x 10 ⁷

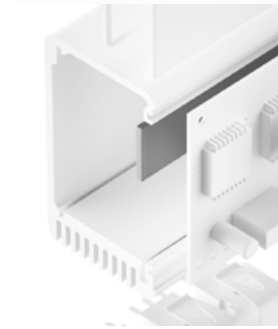
Measurement technique according to: 'ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 1.5 mm / 2.0 mm

SILICONE GAP FILLER PAD TEL-R-SI

HIGHLY THERMALLY CONDUCTIVE ELASTOMER / LOW VOLATILE SILOXANES (LV)

TEL-R-SI is a low dielectric, high performance thermally conductive LV silicone gap filler for an optimised thermal coupling between electronic packages and heat sinks even over large gaps or big tolerances. Through the specific formulation and filling with highly thermally conductive particles an extraordinary high anisotropic thermal conductivity is reached. Its conformal surface structure and extreme softness guarantee a very good compliance to the contact surfaces at very low pressure. Thus the total thermal resistance is minimised. The elastomer shows a low dielectric strength.



PROPERTIES

- High surface compliance and extremely soft
- Low volatile siloxane content (LV)
- Thermal conductivity: 15 W/mK (anisotropic)
- Low dielectric
- Extraordinary chemical resistance and longterm stability
- Shock absorbing

AVAILABILITY

- Sheet 150 x 150 mm (Thickness 0.25 – 1.5 mm)
- Sheet 140 x 140 mm (Thickness 2.0 – 3.0 mm)
- Double-side self tacky (TEL-RXXXX-SI)
- Die cut parts
- Kiss cut parts on sheet

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs und IGBTs
- Power diodes or AC/DC converters
- Power modules
- CPUs

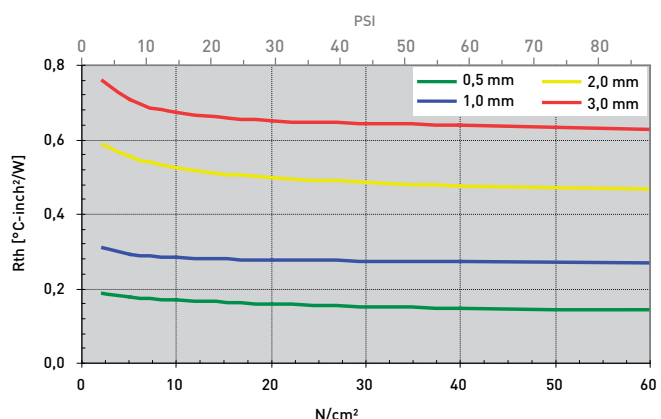
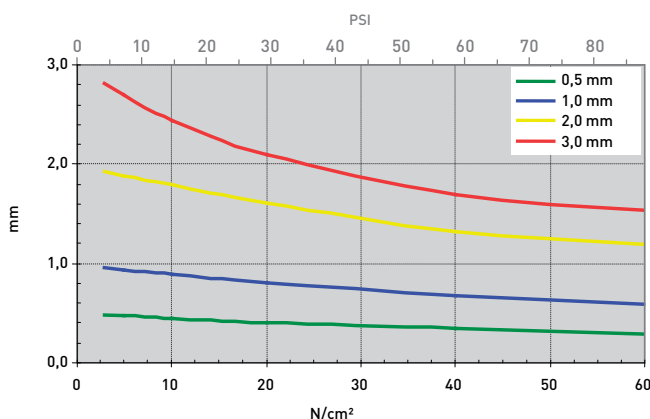
For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

PROPERTY	UNIT	TEL-R0500-SI	TEL-R1000-SI	TEL-R2000-SI
MATERIAL				
Colour		Black	Black	Black
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20
Hardness	Shore 00	55	55	55
Flammability (Equivalent)	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance¹ @ 90 PSI Thickness	°C-inch²/W (mm)	0.15 (0.30)	0.27 (0.60)	0.47 (1.20)
Resistance¹ @ 30 PSI @ Thickness	°C-inch²/W (mm)	0.16 (0.41)	0.28 (0.81)	0.50 (1.61)
Resistance¹ @ 10 PSI @ Thickness	°C-inch²/W (mm)	0.18 (0.47)	0.29 (0.93)	0.54 (1.85)
Thermal Conductivity	W/mK	15	15	15
Operating Temperature Range	°C	- 50 to + 180	- 50 to + 180	- 50 to + 180
ELECTRICAL				
Dielectric Strength	kV/mm	1.0	1.0	1.0
Volume Resistivity	Ohm - cm	≥ 1 x 10¹²	≥ 1 x 10¹²	≥ 1 x 10¹²

Measurement technique according to: ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Thicknesses: 0.25 mm / 0.5 mm / 1.5 mm / 1.0 mm / 2.0 mm / 3.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TEL-Z-SI

HIGHLY THERMALLY CONDUCTIVE ELASTOMER / LOW VOLATILE SILOXANES (LV)

TEL-Z-SI is a non dielectric high performance thermally conductive LV silicone foil for an optimised thermal coupling between electronic packages and heat sinks even over large gaps or big tolerances. Through the specific formulation and filling an extraordinary high anisotropic thermal conductivity is reached. Its conformal surface structure and high softness guarantee a very good compliance to the contact surfaces at low pressure. Thus the total thermal resistance is minimised.



PROPERTIES

- High surface compliance and softness
- Low volatile siloxane content (LV)
- Non dielectric
- No paint wetting impairment
- Thermal conductivity: 50 W/mK (anisotropic)
- Extraordinary chemical resistance and longterm stability
- Shock absorbing

AVAILABILITY

- Sheet 140 x 140 mm (TEL-ZXXX-SI)
- Die cut parts
- Optional with adhesive stripes or dots (TEL-ZXXX-SI-A1)

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs or IGBTs
- Power diodes or AC/DC converters
- Power modules

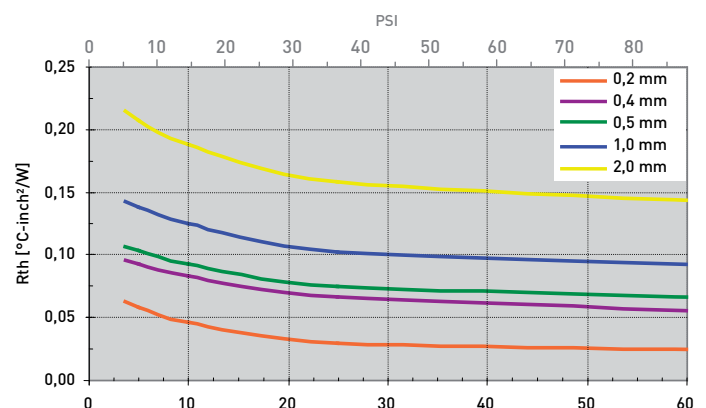
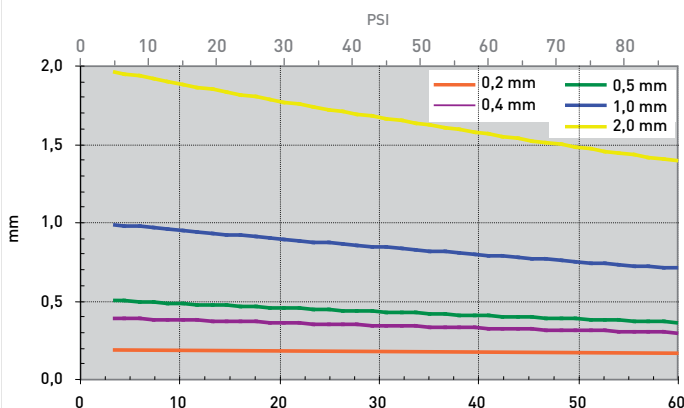
For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

PROPERTY	UNIT	TEL-Z0200-SI	TEL-Z0500-SI	TEL-Z1000-SI
MATERIAL				
Colour		Graphite filled silicone elastomere Black	Graphite filled silicone elastomere Black	Graphite filled silicone elastomere Black
Thickness	mm	0.2 ±0.05	0.5 ±0.05	1.0 ±0.10
Hardness	Shore 00	75	75	75
No Paint Wetting Impairment Substances [PWIS] ¹		Passed	Passed	Passed
Flammability	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ² @ 90 PSI @ Thickness	°C-inch ² /W (mm)	0.020 [0.16]	0.060 [0.33]	0.09 [0.70]
Resistance ² @ 30 PSI @ Thickness	°C-inch ² /W (mm)	0.027 [0.18]	0.075 [0.48]	0.11 [0.91]
Resistance ² @ 10 PSI @ Thickness	°C-inch ² /W (mm)	0.050 [0.19]	0.095 [0.49]	0.13 [0.97]
Thermal Conductivity	W/mK	50	50	50
Operating Temperature Range	°C	- 50 to + 180	- 50 to + 180	- 50 to + 180
ELECTRICAL				
Volume Resistivity	Ohm - cm	< 50.000	< 50.000	< 50.000

Measurement technique according to: ¹P-VW 3-10.7 57650 Temp. Test, ²ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.
Shelf life adhesive: 6 months when stored in original packaging at room temperature and 50% relative humidity.

Thicknesses: 0.2 mm / 0.4 mm / 0.5 mm / 1.0 mm / 2.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TEL-YSS-SI

VERY SOFT, HIGHLY THERMALLY CONDUCTIVE ELASTOMER / LOW VOLATILE SILOXANES (LV)

TEL-YSS-SI is a non dielectric high performance thermally conductive LV silicone gap filler for an optimised thermal coupling between electronic packages and heat sinks even over large gaps or big tolerances. Through the specific formulation and filling an extraordinary high anisotropic thermal conductivity is reached. Its conformal surface structure and extraordinary softness guarantee a very good compliance to the contact surfaces at low pressure. Thus the total thermal resistance is minimised.



PROPERTIES

- High surface compliance and extraordinary soft
- Low volatile siloxane content (LV)
- Non dielectric
- Thermal conductivity: 16 W/mK (anisotropic)
- Extraordinary chemical resistance and longterm stability
- Shock absorbing

AVAILABILITY

- Sheet 130 x 130 mm (TEL-YSSXXX-SI)
- Die cut parts
- Optional with adhesive stripes or dots (TEL-YSSXXX-SI-A1)

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs und IGBTs
- Power diodes or AC/DC converters
- Power modules

For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

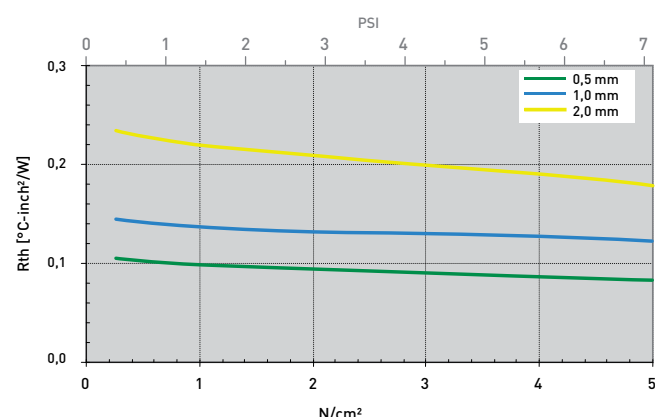
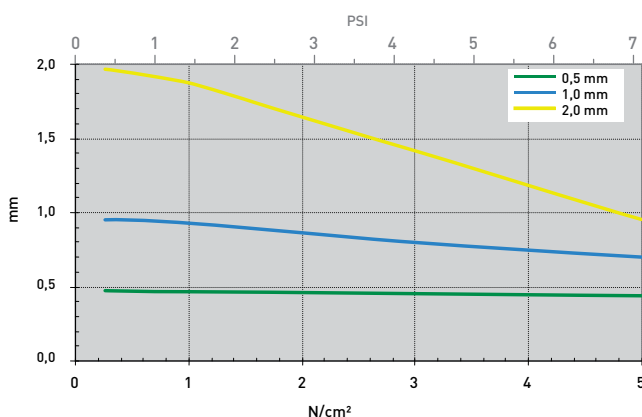
PROPERTY	UNIT	TEL-YSS0500-SI	TEL-YSS1000-SI	TEL-YSS2000-SI
MATERIAL				
		Graphite filled silicone elastomere	Graphite filled silicone elastomere	Graphite filled silicone elastomere
Colour		Black	Black	Black
Thickness	mm	0.5 ±0.05	1.0 ±0.10	2.0 ±0.20
Hardness	Shore 00	40	40	40
Flammability	UL 94	V0	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes	Yes
THERMAL				
Resistance ¹ @ 7.5 PSI @ Thickness	°C-inch ² /W (mm)	0.083 (0.42)	0.124 (0.700)	0.180 (0.954)
Resistance ¹ @ 3.5 PSI @ Thickness	°C-inch ² /W (mm)	0.089 (0.45)	0.129 (0.785)	0.205 (1.550)
Resistance ¹ @ 1.5 PSI @ Thickness	°C-inch ² /W (mm)	0.100 (0.47)	0.137 (0.934)	0.220 (1.874)
Thermal Conductivity ¹	W/mK	16	16	16
Operating Temperature Range	°C	- 50 to + 180	- 50 to + 180	- 50 to + 180
ELECTRICAL				
Volume Resistivity	Ohm - cm	< 50.000	< 50.000	< 50.000

Measurement technique according to: ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Shelf life adhesive: 6 months when stored in original packaging at room temperature and 50% relative humidity.

Thicknesses: 0.5 mm / 1.0 mm / 1.5 mm / 2.0 mm / 3.0 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



SILICONE GAP FILLER PAD TEL-ZS-SI

SOFT, HIGHLY THERMALLY CONDUCTIVE ELASTOMER / LOW VOLATILE SILOXANES (LV)

TEL-ZS-SI is a non dielectric high performance thermally conductive LV silicone foil for an optimised thermal coupling between electronic packages and heat sinks even over large gaps or big tolerances. Through the specific formulation and filling an extraordinary high anisotropic thermal conductivity is reached. Its conformal surface structure and high softness guarantee a very good compliance to the contact surfaces at low pressure. Thus the total thermal resistance is minimised.



PROPERTIES

- High surface compliance and softness
- Low volatile siloxane content (LV)
- Non dielectric
- Thermal conductivity: 20 W/mK (anisotropic)
- Extraordinary chemical resistance and longterm stability
- Shock absorbing

AVAILABILITY

- Sheet 120 x 120 mm (TEL-ZSXXX-SI)
- Die cut parts
- Optional with adhesive stripes or dots (TEL-ZSXXX-SI-A1)

APPLICATION EXAMPLES

Thermal link of:

- MOSFETs or IGBTs
- Power diodes or AC/DC converters
- Power modules

For use in Switch mode power supplies / Motor control units / Automotive engine management systems / UPS units / Solar systems

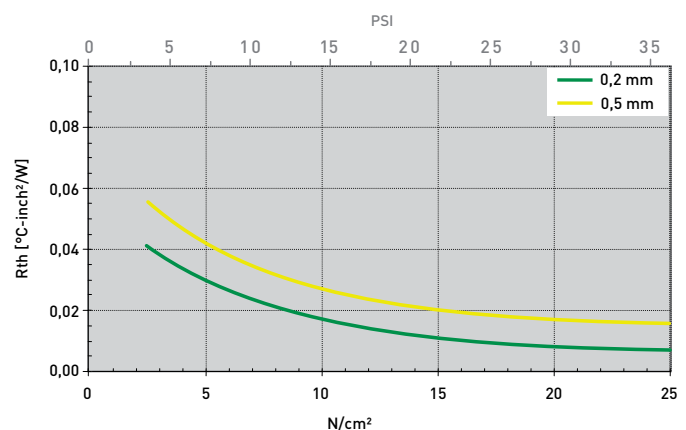
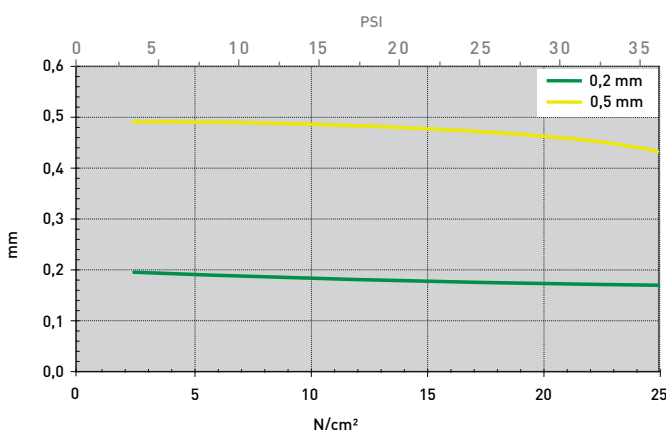
PROPERTY	UNIT	TEL-ZS0200-SI	TEL-ZS0500-SI
MATERIAL			
Colour		Carbon filled silicone elastomere Black	Carbon filled silicone elastomere Black
Thickness	mm	0.2 ±0.05	0.5 ±0.05
Hardness	Shore 00	60	60
Flammability (Equivalent)	UL 94	V0	V0
RoHS Conformity	2015 / 863 / EU	Yes	Yes
THERMAL			
Resistance ¹ @ 35 PSI @ Thickness	°C-inch ² /W (mm)	0.007 [0.17]	0.018 [0.44]
Resistance ¹ @ 15 PSI @ Thickness	°C-inch ² /W (mm)	0.017 [0.18]	0.027 [0.48]
Resistance ¹ @ 7 PSI @ Thickness	°C-inch ² /W (mm)	0.030 [0.19]	0.042 [0.49]
Thermal Conductivity ¹	W/mK	20	20
Operating Temperature Range	°C	- 40 to + 150	- 40 to + 150
ELECTRICAL			
Volume Resistivity	Ohm - cm	< 50,000	< 50,000

Test Methods: ¹ ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

Shelf life adhesive: 6 months when stored in original packaging at room temperature and 50% relative humidity.

Thicknesses: 0.2 mm / 0.3 mm / 0.5 mm

mm vs. N/cm² (PSI) / Rth vs. N/cm² (PSI)



2-PART SILICONE GAP FILLER TDG-L-SI-2C-Y

DISPENSABLE / 2 PARTS / LOW VOLATILE SILOXANES (LV) / FORM-IN-PLACE

TDG-L-SI-2C-Y is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



PROPERTIES

- Dispensable 2-part silicone
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 2.0 W/mK
- Remains elastic after polymerisation
- Zero stress on components
- Heat accelerated curing
- Shock absorbing

AVAILABILITY

- Optional in blue colour:
- TDG-L-SI-2C
- Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- Pail 2 x 25 kg / 2 x 35 kg
- On request

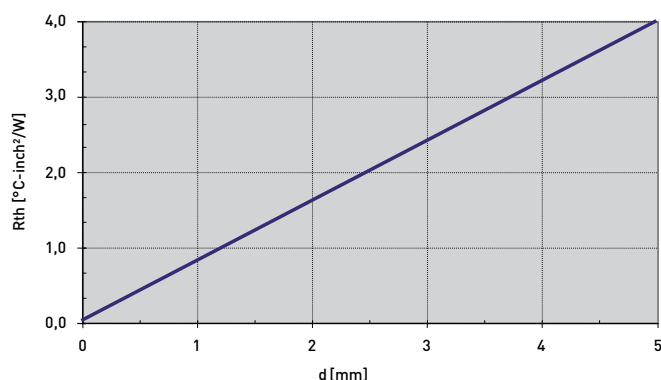
APPLICATION EXAMPLES

Thermal link of:

- FPBGA
 - Capacitors
 - Heat Pipes
 - BGA
- For use in Automotive applications / Telecommunication / Multimedia / Industrial PCs

PROPERTY	UNIT	A Part	B Part
MATERIAL			
Colour		Silicone Yellow	Silicone White
Density @ 25 °C	g/cm³	1.9	1.9
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	52	52
Viscosity (Brookfield @ 10 rpm, 25 °C)	Pas	260	260
Viscosity (mixed) (Brookfield @ 10 rpm, 25 °C)	Pas	260	260
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 120	> 120
Curing Time @ 25 °C / 100 °C		< 24h / 15 - 30 min	< 24h / 15 - 30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
Outgasing ¹	TML / CVCM / WVR %	0.16 / 0.03 / 0.04	0.16 / 0.03 / 0.04
No Paint Wetting Impairment Substances (PWIS) ²		Passed	Passed
Flammability	UL 94	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ³	W/mK	2.0	2.0
Operating Temperature	°C	- 50 to + 150	- 50 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	1 x 10 ¹⁰	1 x 10 ¹⁰

Measurement technique according to: ¹ ASTM E 595, ² P-VW 3-10.7 57650 Temp. Test, ³ ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.



2-PART SILICONE GAP FILLER TDG-T-SI-2C

DISPENSABLE / 2 PARTS / LOW VOLATILE SILOXANES (LV) / FORM-IN-PLACE

TDG-T-SI-2C is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



PROPERTIES

- Dispensable 2-part silicone
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 3.0 W/mK
- Remains elastic after polymerisation
- Zero stress on components
- Heat accelerated curing
- Shock absorbing

AVAILABILITY

- Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- Pail 2 x 25 kg / 2 x 35 kg
- On request

APPLICATION EXAMPLES

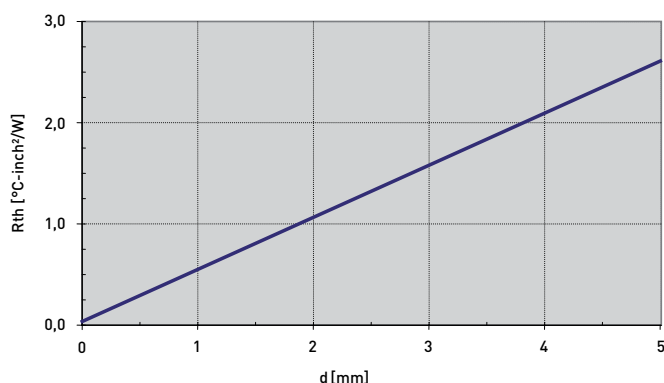
Thermal link of:

- FPBGA
- Capacitors
- Heat Pipes
- BGA

For use in Automotive applications / Telecommunication / Multimedia / Industrial PCs

PROPERTY	UNIT	A Part	B Part
MATERIAL		Silicone	Silicone
Colour		Blue	White
Density @ 25 °C	g/cm ³	2.75	2.75
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	55	55
Viscosity (Brookfield @ 10 rpm, 25 °C)	Pas	290	260
Viscosity (mixed) (Brookfield @ 10 rpm, 25 °C)	Pas	275	275
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 120	> 120
Curing Time @ 25 °C / 100 °C		< 15h / 15 - 30 min	< 15h / 15 - 30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
Outgasing ¹	TML / CVCM / WVR %	0.07 / 0.02 / 0.02	0.07 / 0.02 / 0.02
No Paint Wetting Impairment Substances (PWIS) ²		Passed	Passed
Flammability	UL 94	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ³	W/mK	3.0	3.0
Operating Temperature	°C	- 50 to + 150	- 50 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	1 x 10 ¹⁰	1 x 10 ¹⁰

Measurement technique according to: ¹ ASTM E 595, ² P-VW 3-10.7 57650 Temp. Test, ³ ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information



2-PART SILICONE GAP FILLER TDG-U-SI-2C

DISPENSABLE / 2 PARTS / LOW VOLATILE SILOXANES (LV) / FORM-IN-PLACE

TDG-U-SI-2C is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



PROPERTIES

- Dispensable 2-part silicone
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 3.6 W/mK
- Remains elastic after polymerisation
- Zero stress on components
- Heat accelerated curing
- Shock absorbing

AVAILABILITY

- Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- Pail 2 x 25 kg / 2 x 35 kg
- On request

APPLICATION EXAMPLES

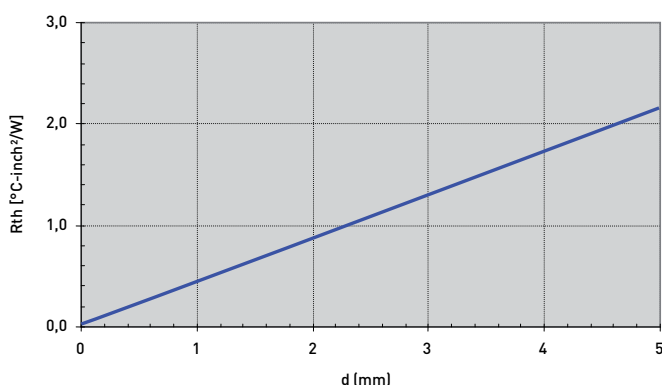
Thermal link of:

- FPBGA
- Capacitors
- Heat Pipes
- BGA

For use in Automotive applications / Telecommunication / Multimedia / Industrial PCs

PROPERTY	UNIT	A Part	B Part
MATERIAL			
Colour		Light Blue	White
Density @ 25 °C	g/cm ³	2.85	2.85
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	38	38
Viscosity (Brookfield @ 10 rpm, 25 °C)	Pas	220	190
Viscosity (mixed) (Brookfield @ 10 rpm, 25 °C)	Pas	260	260
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 100	> 100
Curing Time @ 25 °C / 100 °C		< 15h / 15 - 30 min	< 15h / 15 - 30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
Outgasing ¹	TML / CVCM / WVR %	0.07 / 0.02 / 0.04	0.07 / 0.02 / 0.04
No Paint Wetting Impairment Substances (PWIS) ²		Passed	Passed
Flammability	UL 94	VO	VO
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ³	W/mK	3.6	3.6
Operating Temperature	°C	- 50 to + 150	- 50 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	1 x 10 ¹⁰	1 x 10 ¹⁰

Measurement technique according to: ¹ ASTM E 595, ² P-VW 3-10.7 57650 Temp. Test, ³ ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.



2-PART SILICONE GAP FILLER TDG-W-SI-2C

DISPENSABLE / 2 PARTS / LOW VOLATILE SILOXANES (LV) / FORM-IN-PLACE

TDG-W-SI-2C is a 2-part dispensable low volatile LV silicone gap filler which is filled with thermally conductive fillers. After curing under heat the system remains elastic. It is characterised by very good dielectric and mechanic properties and is suited for compensating extreme tolerances and spaces at non-coplanar systems. Its thixotropic behaviour allows for a definite placement and cure-in-place. It has a natural low level tack that enhances a good thermal contact. Due to its negligible and controlled volatile content it is suited for environments where volatile silicones and paint wetting impairment are critical.



PROPERTIES

- Dispensable 2-part silicone
- Low volatile siloxane content (LV)
- No paint wetting impairment
- Thermal conductivity: 4.5 W/mK
- Remains elastic after polymerisation
- Zero stress on components
- Heat accelerated curing
- Shock absorbing

AVAILABILITY

- Cartridges 2 x 25 ml / 2 x 100 ml / 2 x 200 ml / 2 x 600 ml
- Pail 2 x 25 kg
- On request

APPLICATION EXAMPLES

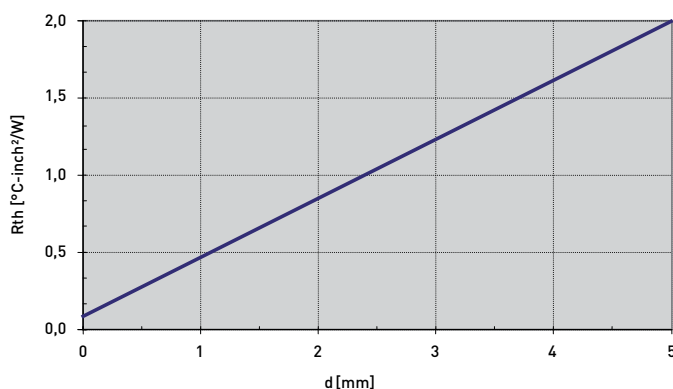
Thermal link of:

- FPBGA
- Capacitors
- Heat Pipes
- BGA

For use in Automotive applications / Telecommunication / Multimedia / Industrial PCs

PROPERTY	UNIT	A Part	B Part
MATERIAL		Silicone	Silicone
Colour		Pink	White
Density @ 25 °C	g/cm³	3.15	3.15
Mixing Ratio	Weight or Volume	1 : 1	1 : 1
Hardness	Shore 00	55	55
Viscosity (Brookfield @ 10 rpm, 25 °C)	Pas	250	250
Viscosity (mixed) (Brookfield @ 10 rpm, 25 °C)	Pas	250	250
Pot Life @ 25 °C and 65 % RH (Time for viscosity to double)	min	> 120	> 120
Curing Time @ 25 °C / 100 °C		< 24 h / 15-30 min	< 24 h / 15-30 min
Shelf Life (from Date of Manufacturing, unopened, @ < 35 °C)	Months	6	6
No Paint Wetting Impairment Substances (PWIS) ¹		Passed	Passed
Flammability	UL 94	V0 (≥ 0.15 mm)	V0 (≥ 0.15 mm)
RoHS Conformity	2015 / 863 / EU	Yes	Yes
TECHNICAL			
Thermal Conductivity ²	W/mK	4.5	4.5
Operating Temperature	°C	- 40 to + 150	- 40 to + 150
Dielectric Strength	kV/mm	> 10	> 10
Volume Resistivity	Ohm - cm	> 1 x 10 ¹⁰	> 1 x 10 ¹⁰

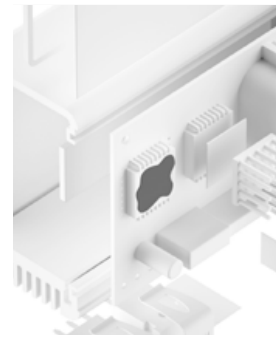
Measurement technique according to: ¹P-VW 3-10.7 57650 Temp. Test, ²ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.



SILICONE GAP FILLER / PUTTY TGL-W-SI

DISPENSABLE

TGL-W-SI is an electrically insulating thermally conductive, highly viscous dispensable form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional curing process. Due to the specific formulation and filling with ceramic particles the material has a very high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



PROPERTIES

- Dispensable
- Almost zero pressure at assembly due to viscoplasticity
- Thermal conductivity: 5.5 W/mK
- Ready-made, no additional curing required

AVAILABILITY

- Cartridges 30 ml
- Tube 250 g
- Pail 2 kg
- Others on request

APPLICATION EXAMPLES

Thermal link of:

- SMD packages
 - Through-hole vias
 - RDRAMs memory modules
 - Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs

PROPERTY	UNIT	TGL-W-SI
MATERIAL		Ceramic filled silicone compound
Colour		Grey
Density	g/cm ³	3.1
Penetration	mm/10	290
RoHS Conformity	2015/863/EU	Yes
THERMAL		
Thermal Conductivity	W/mK	5.5
Operating Temperature Range	°C	- 40 to + 150
ELECTRICAL		
Dielectric Strength	kV / mm	10
Volume Resistance	Ohm - cm	1.0 x 10 ¹³

All data without warranty and subject to change. Please contact us for further data and information.

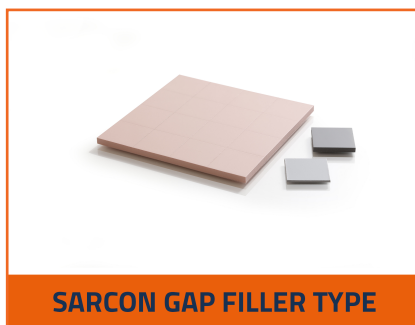


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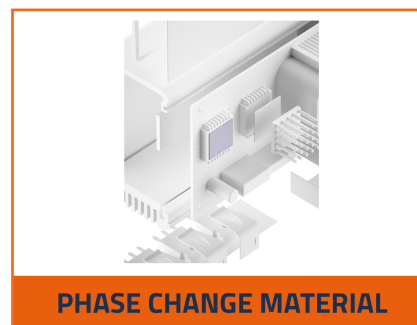
VORES PRODUKTSORTIMENT INKLUDERER:



SARCON GREASE TYPE



SARCON GAP FILLER TYPE



PHASE CHANGE MATERIAL



EKSTRUDEREDE



CLIPS



KØLEPROFILER

VI FØRER PRODUKTER INDENFOR KATEGORIERNE:



AUTOMATIK



HVAC & BYGNINGS-
AUTOMATIK



ELVARME

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